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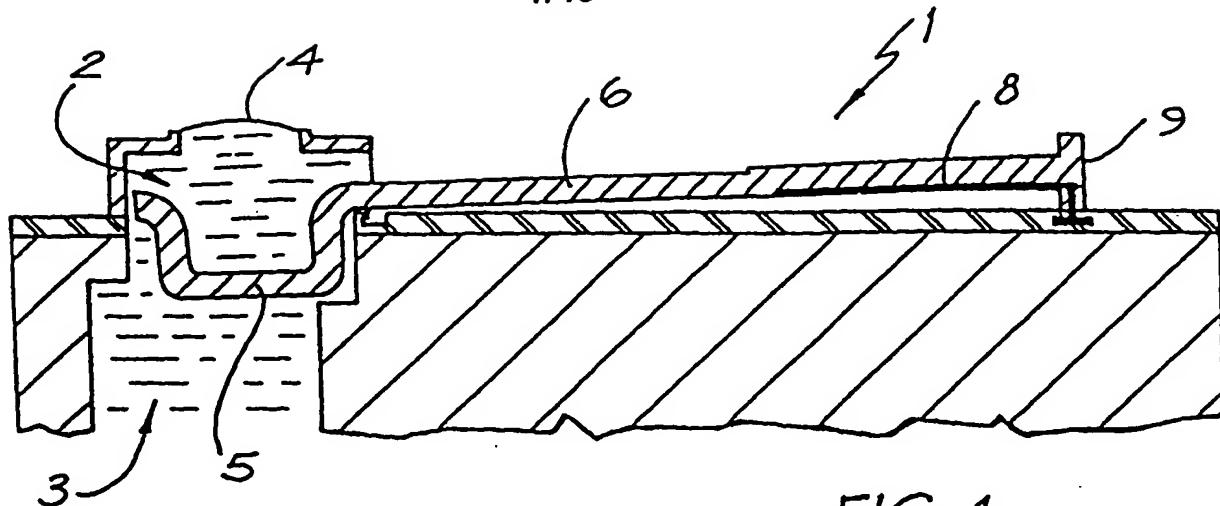


FIG. 1.

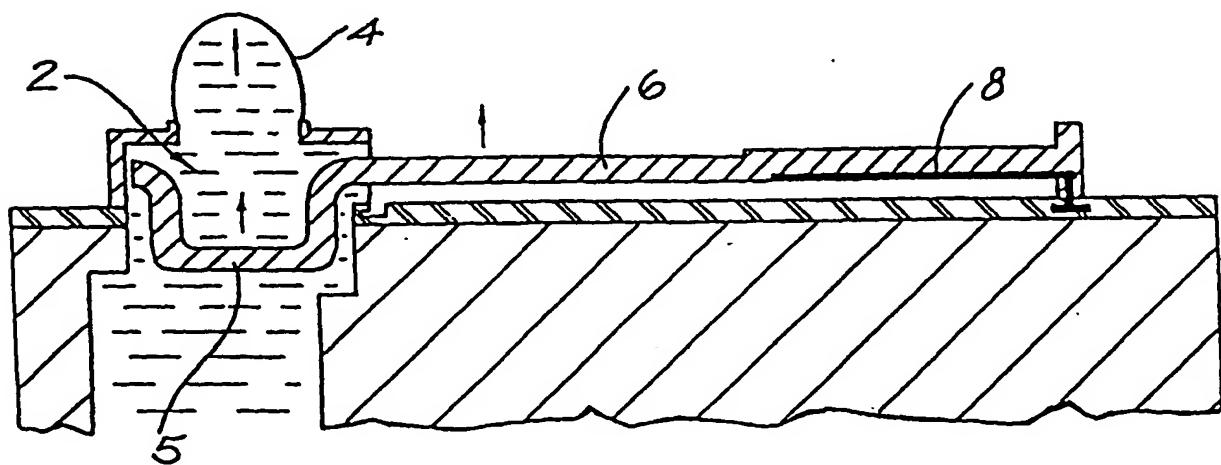


FIG. 2

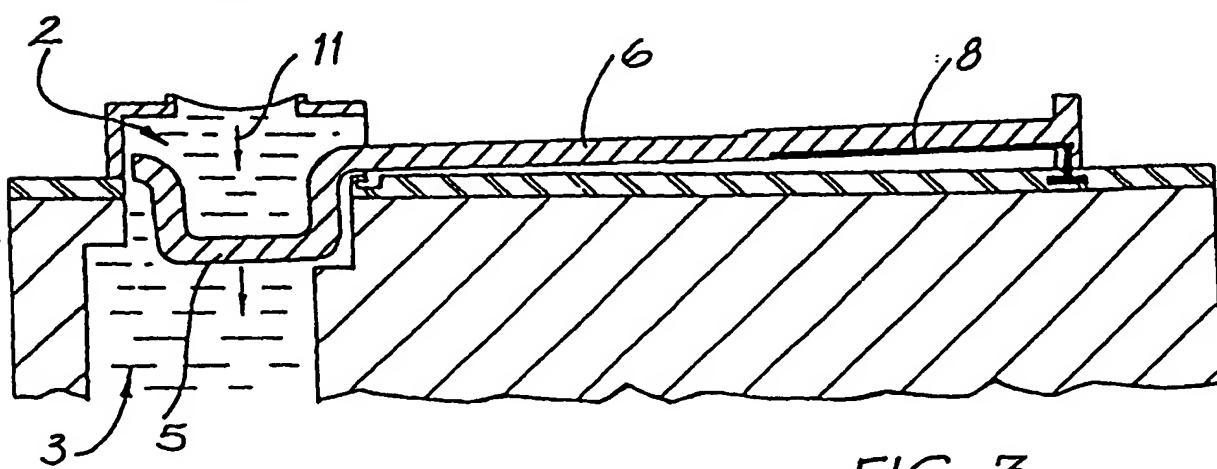
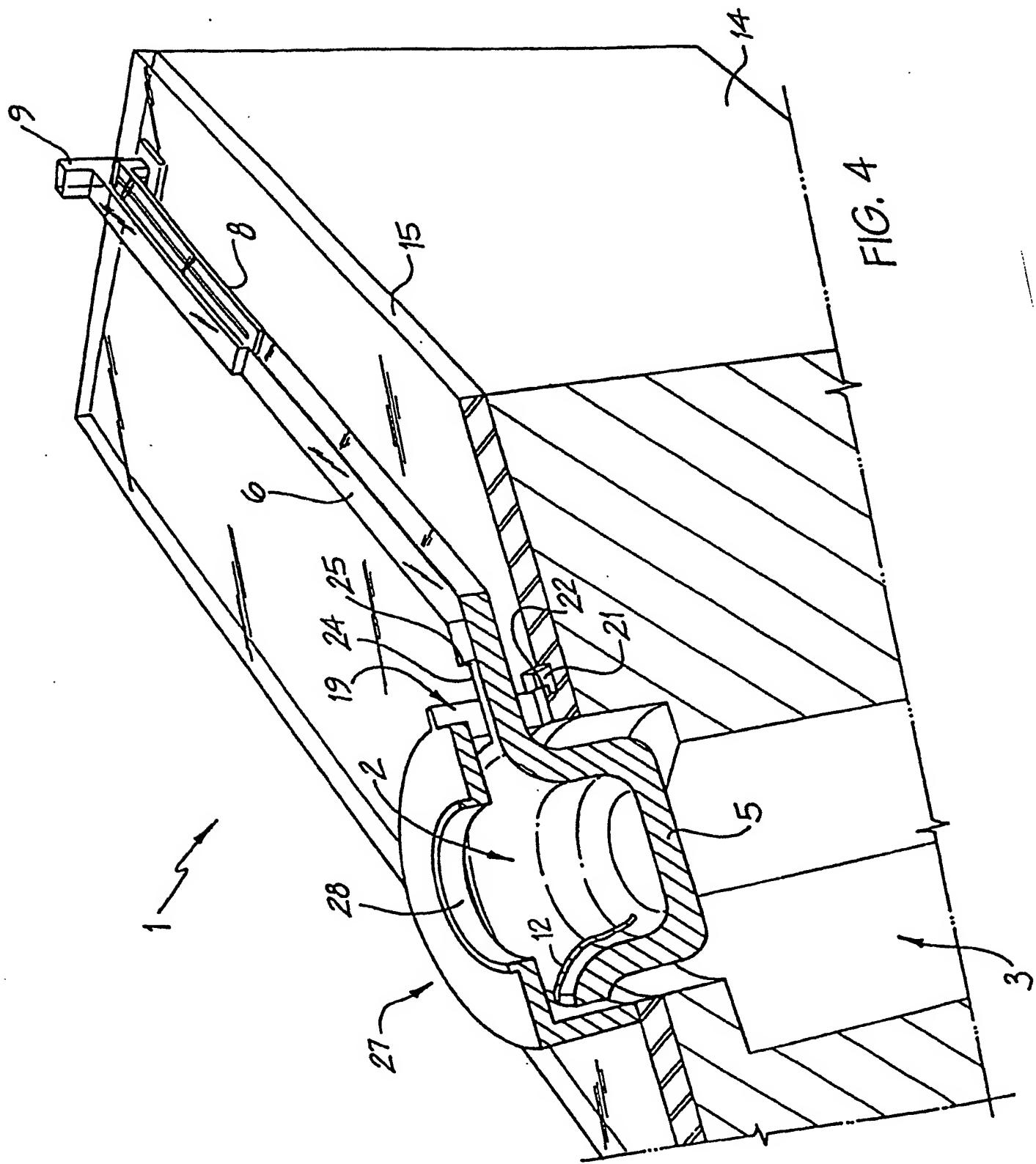
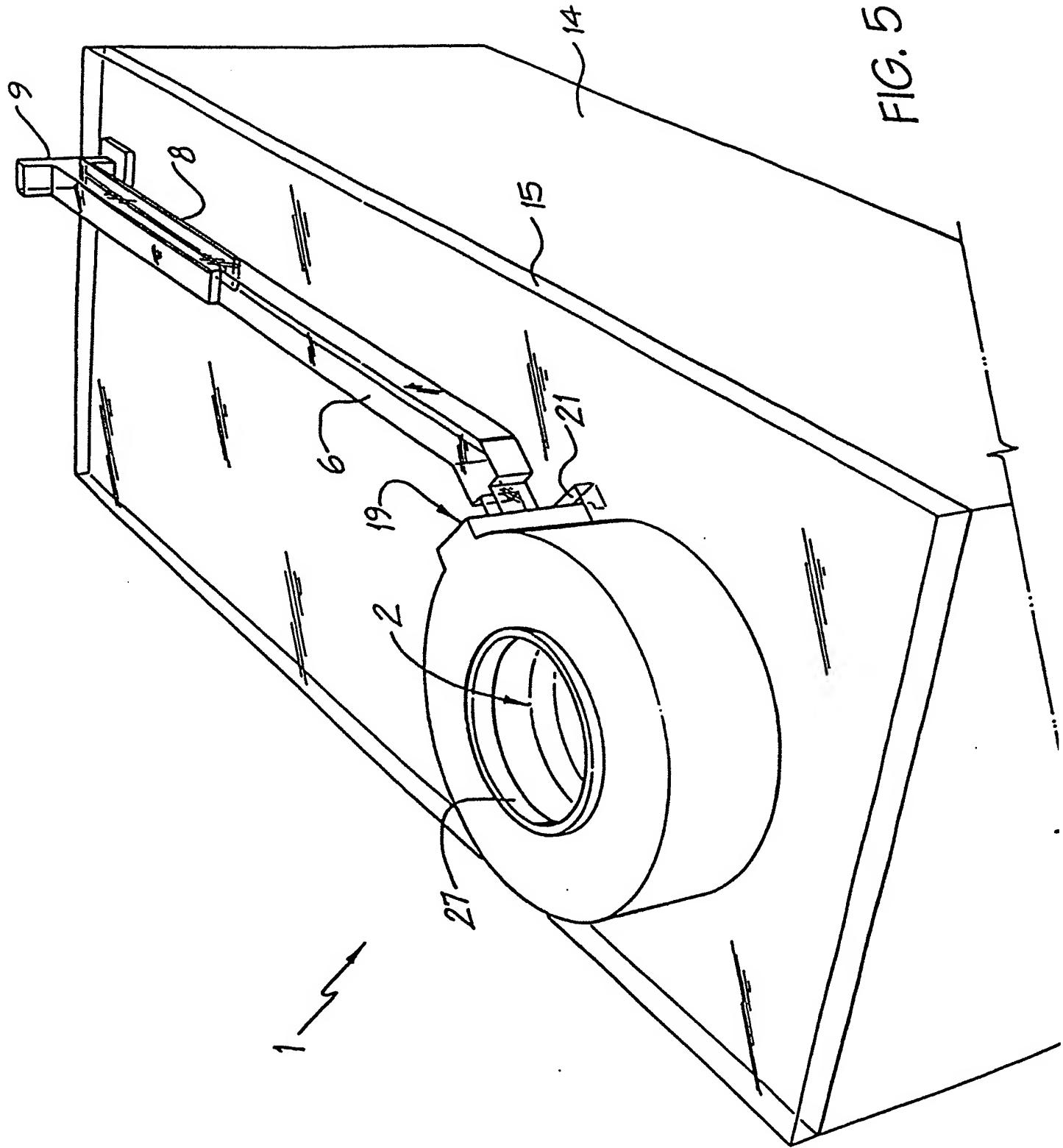


FIG. 3

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FIG. 6A

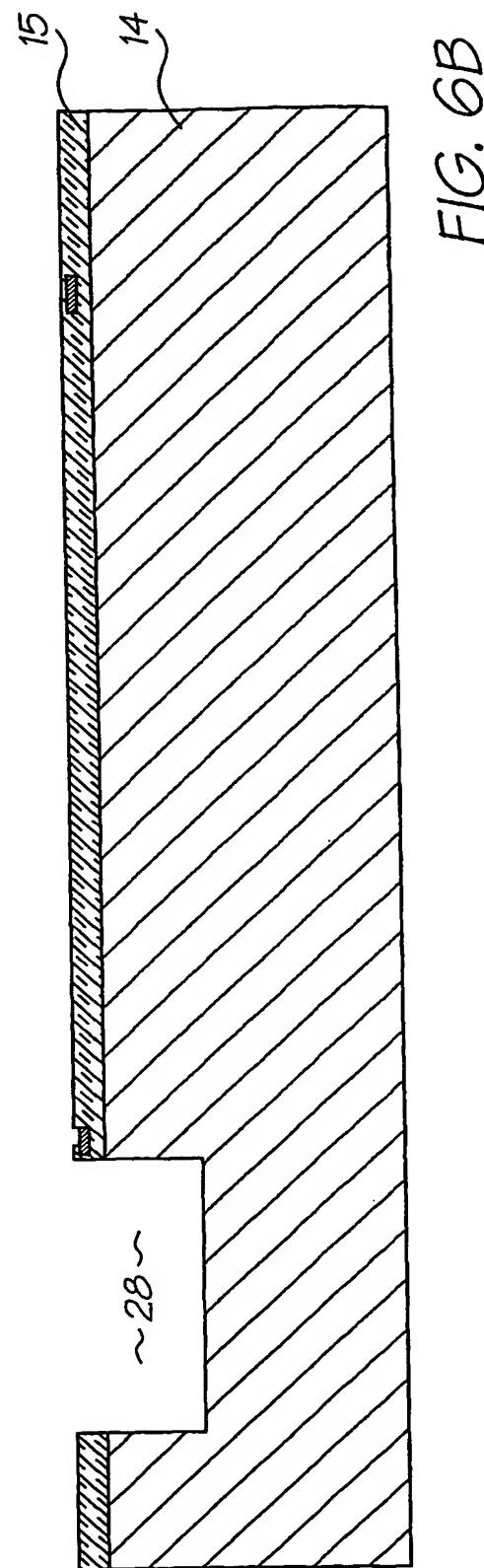
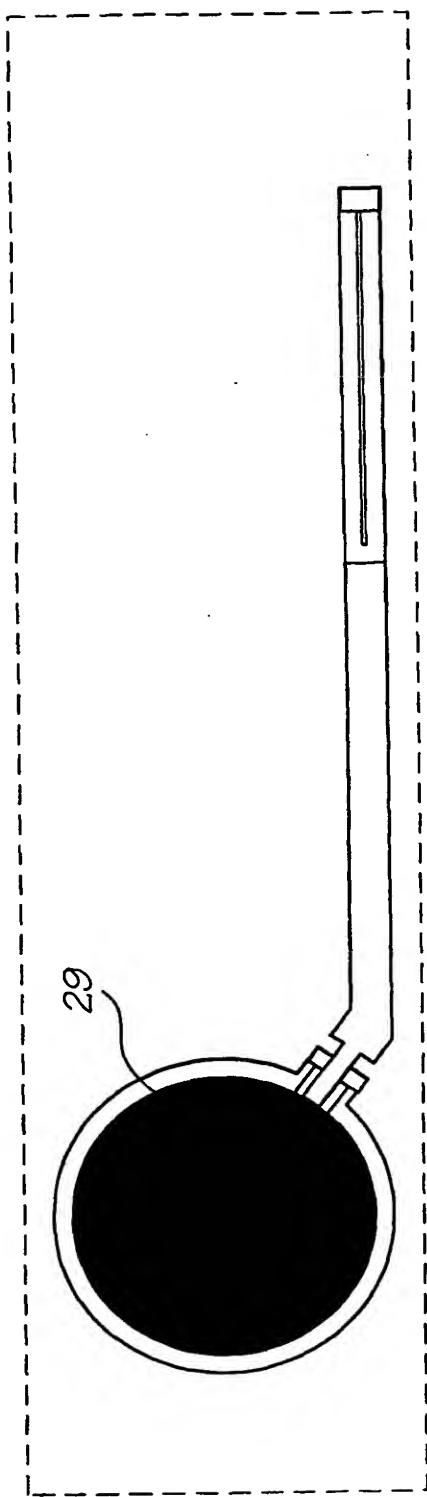
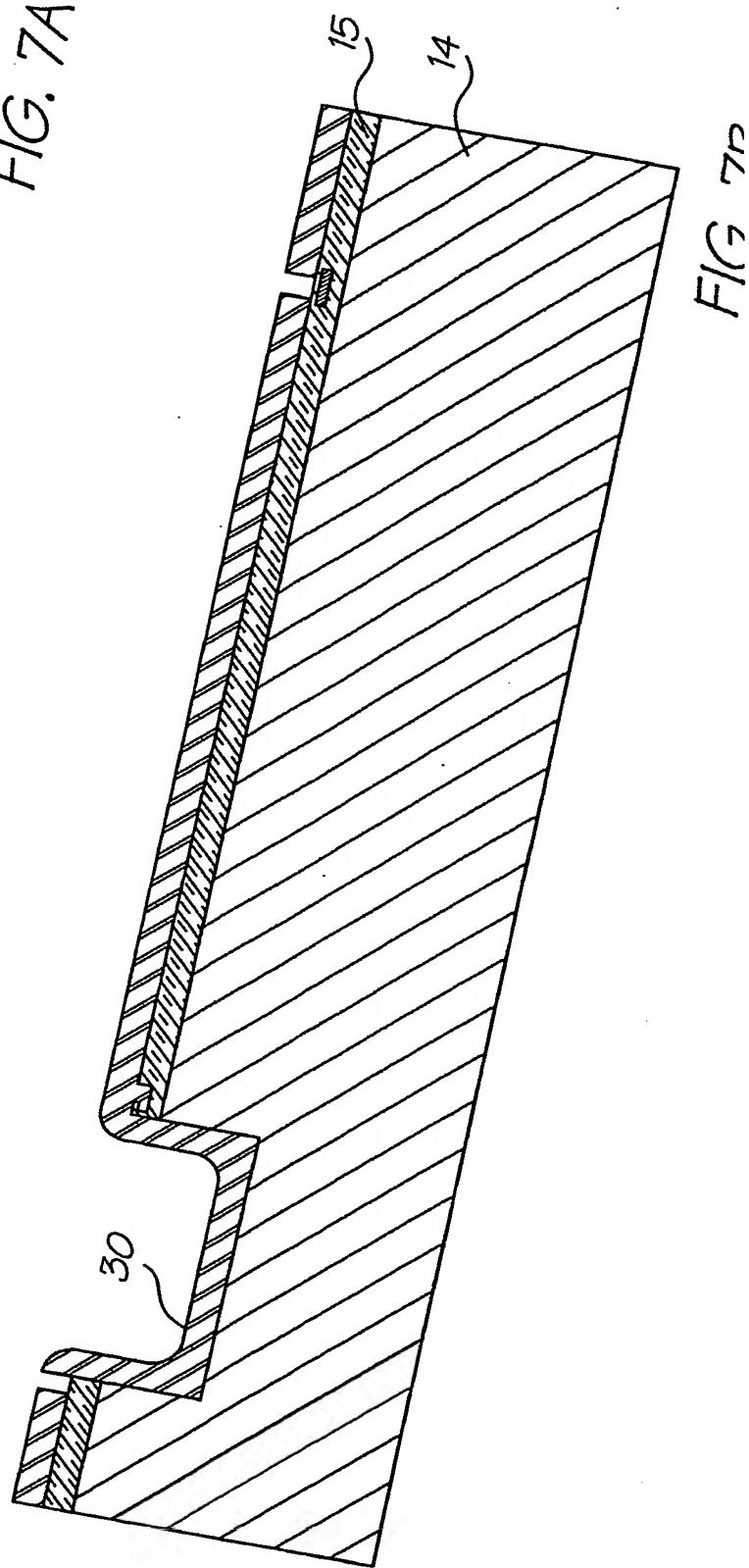
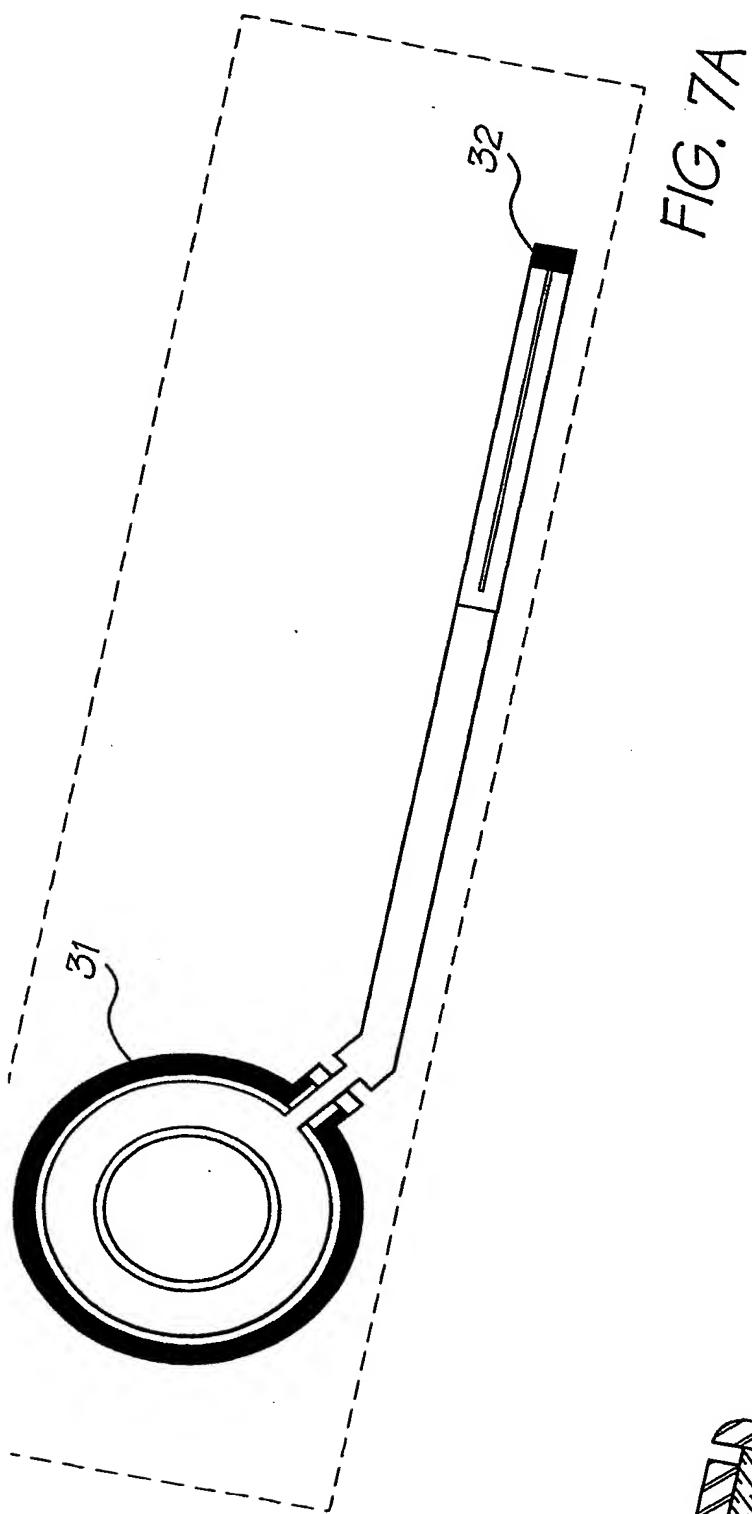


FIG. 6B

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FIG. 8A

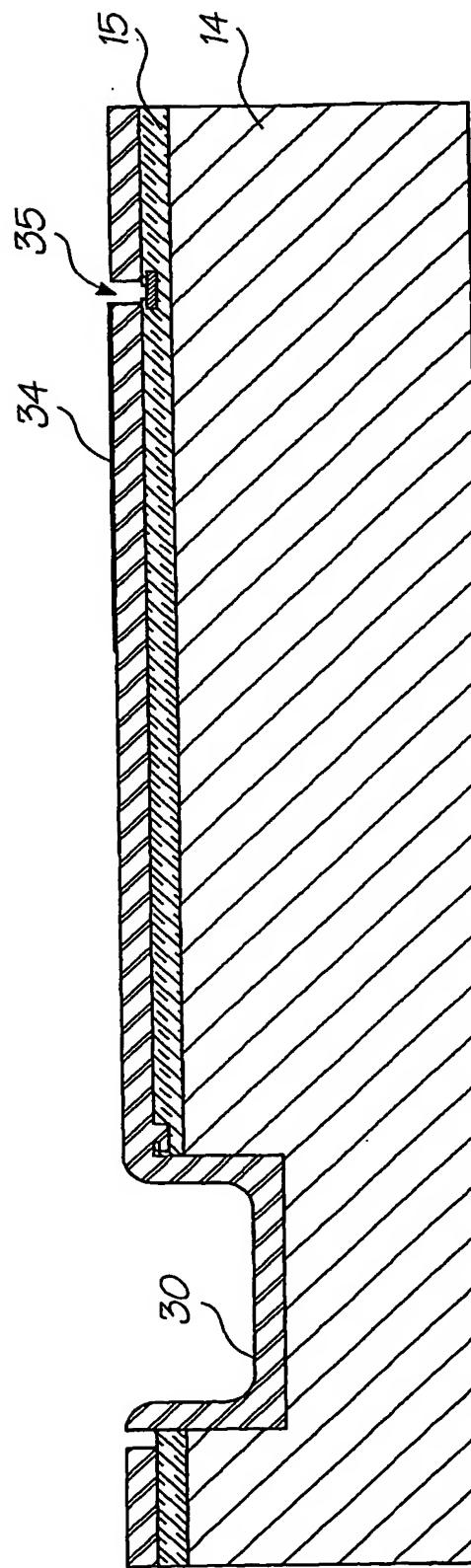
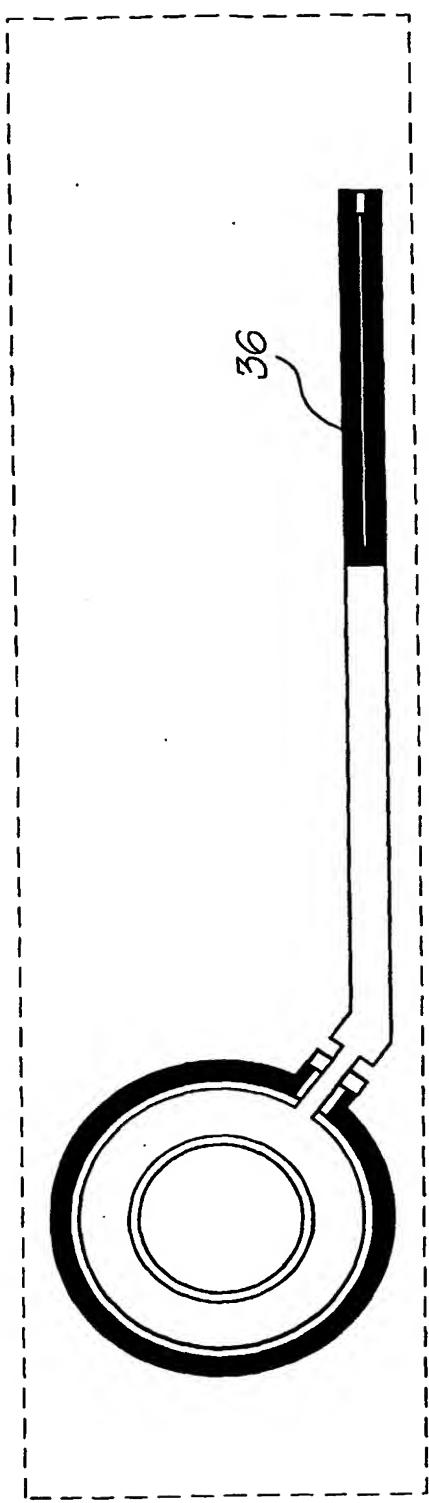


FIG. 8B

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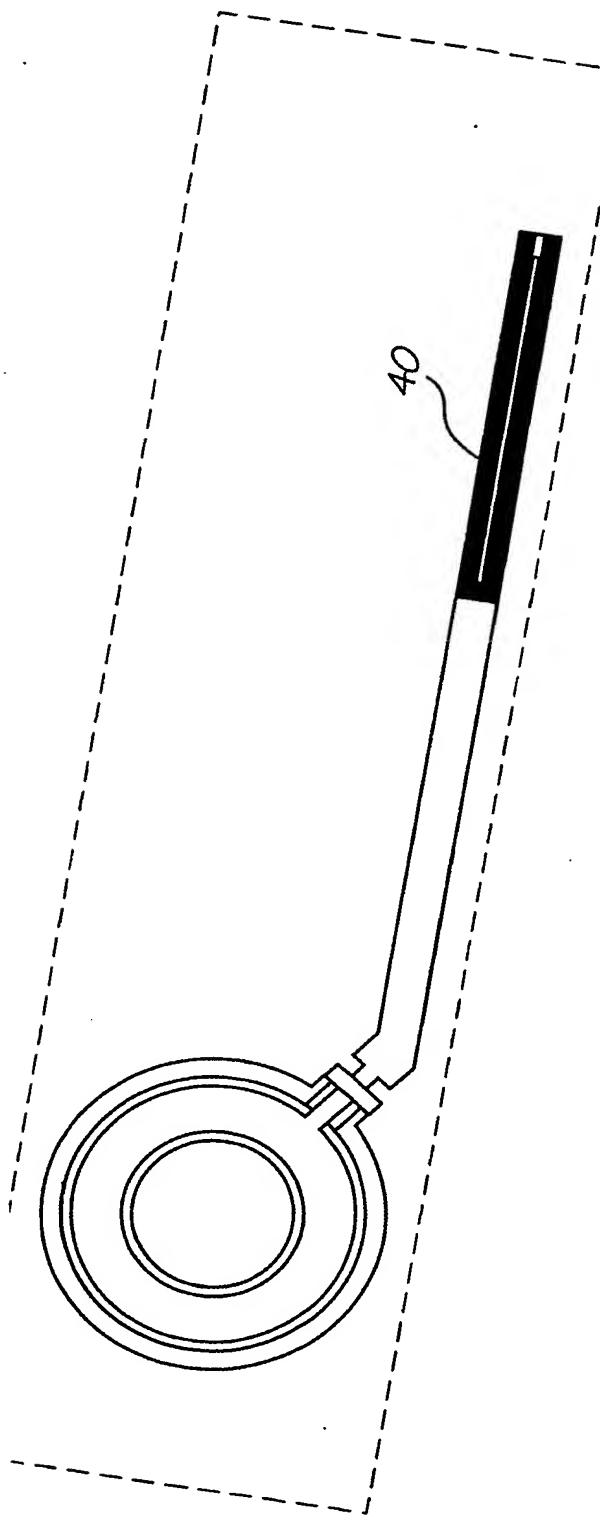


FIG. 9A

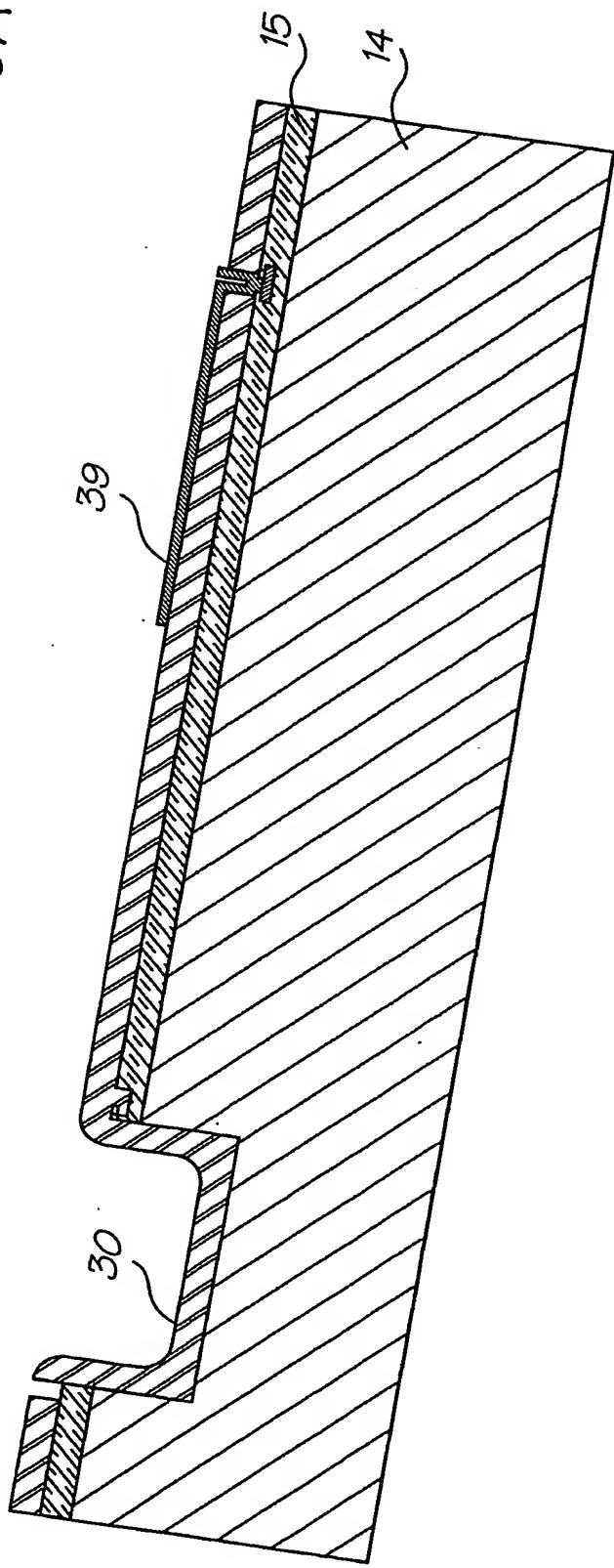


FIG. 9R

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FIG. 10A

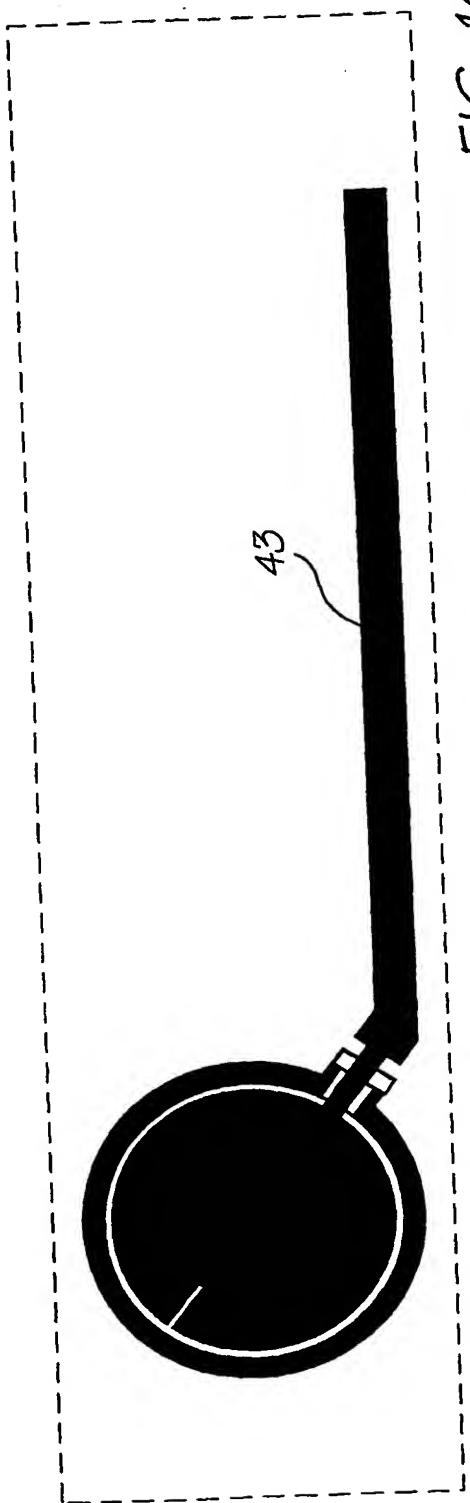
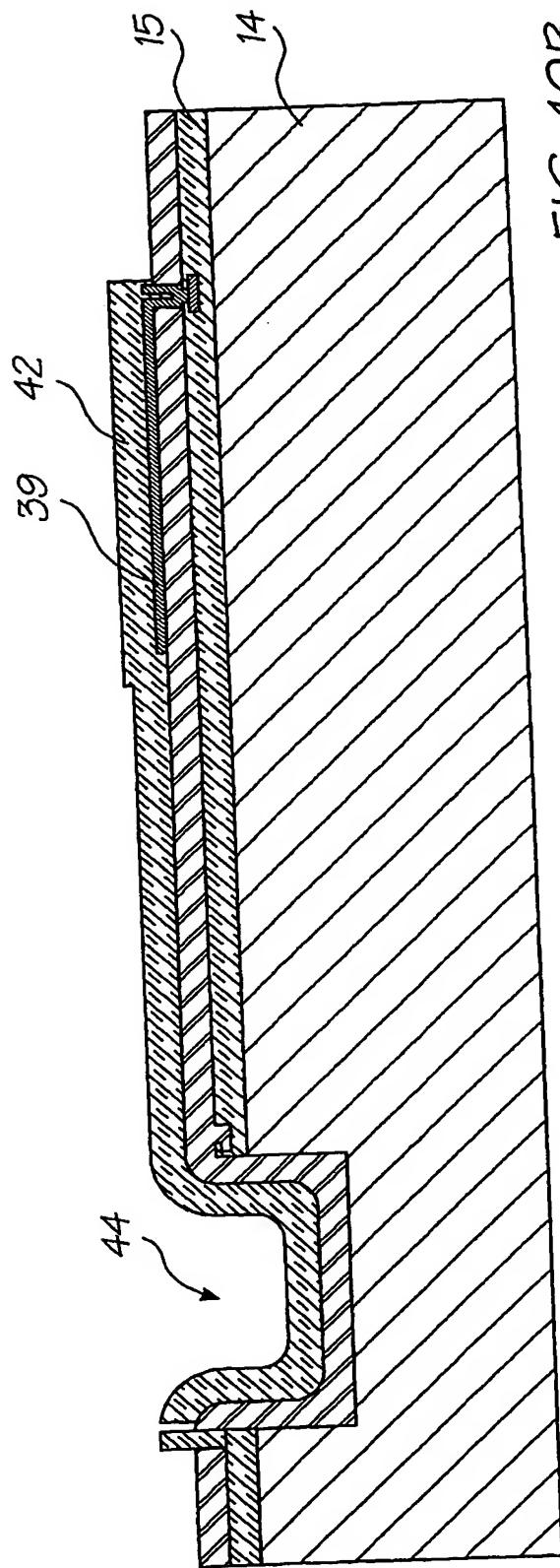


FIG. 10B



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FIG. 11A

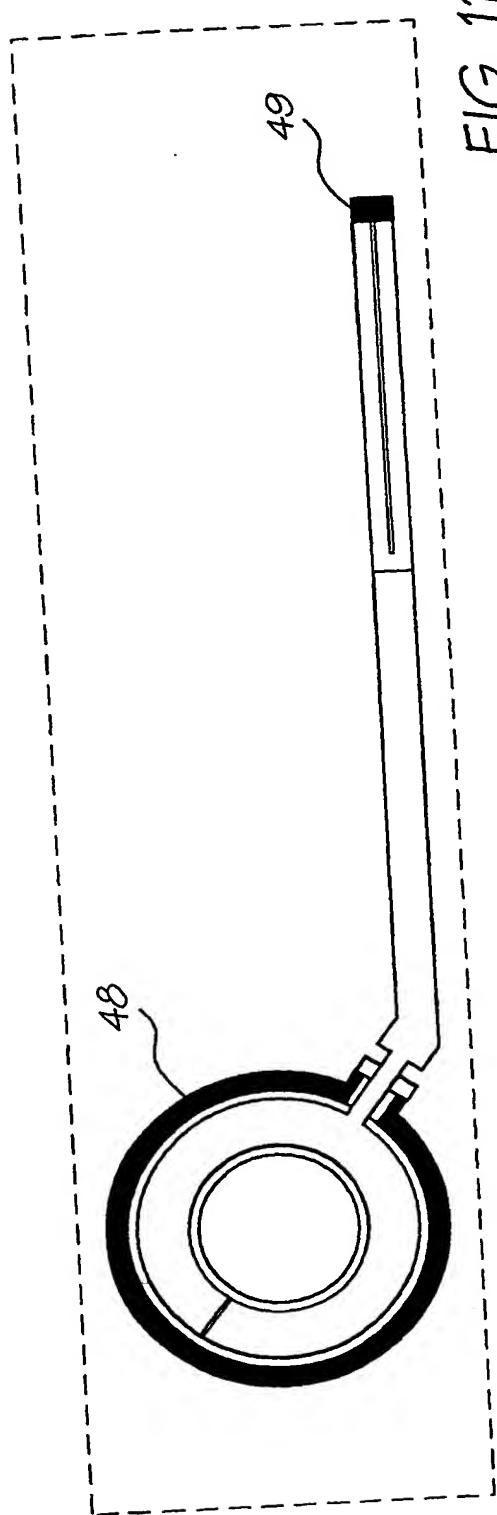
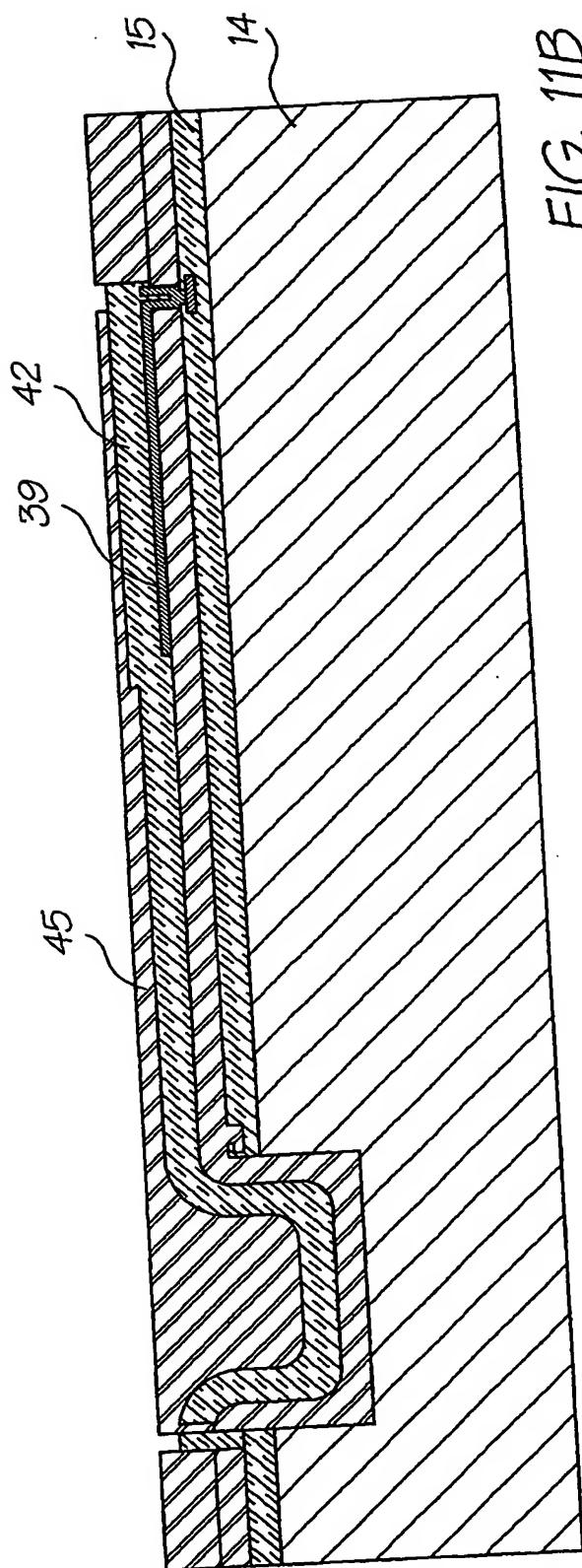


FIG. 11B



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FIG. 12A

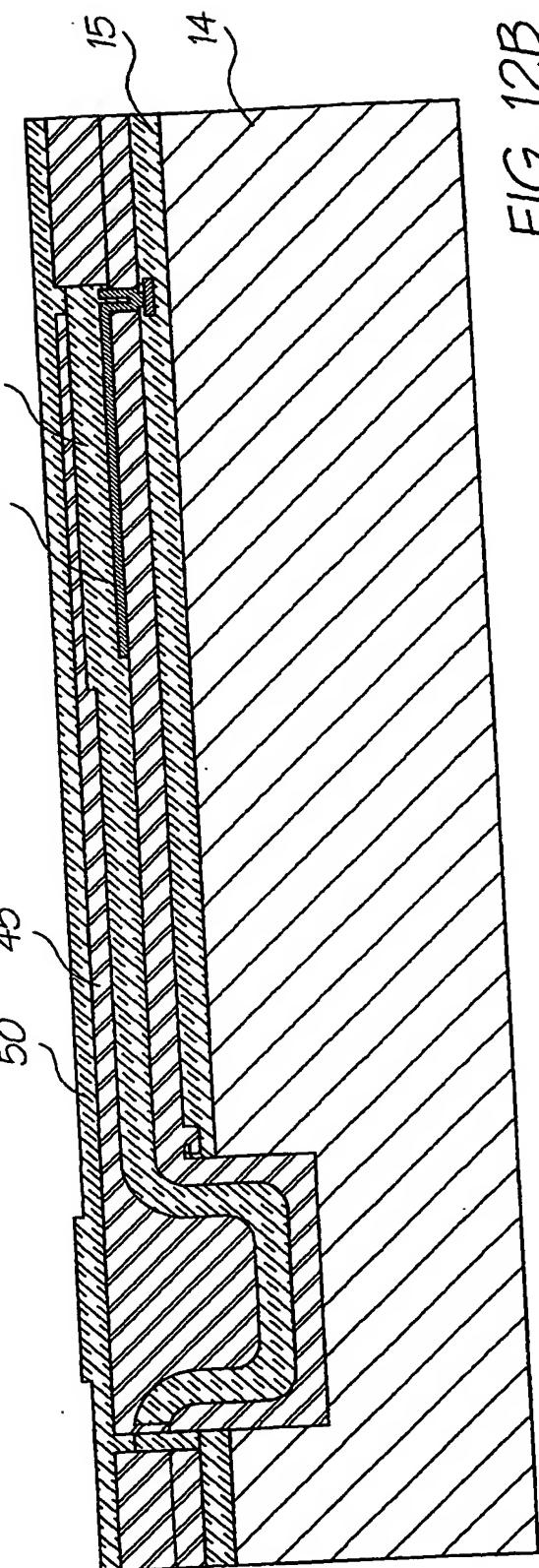
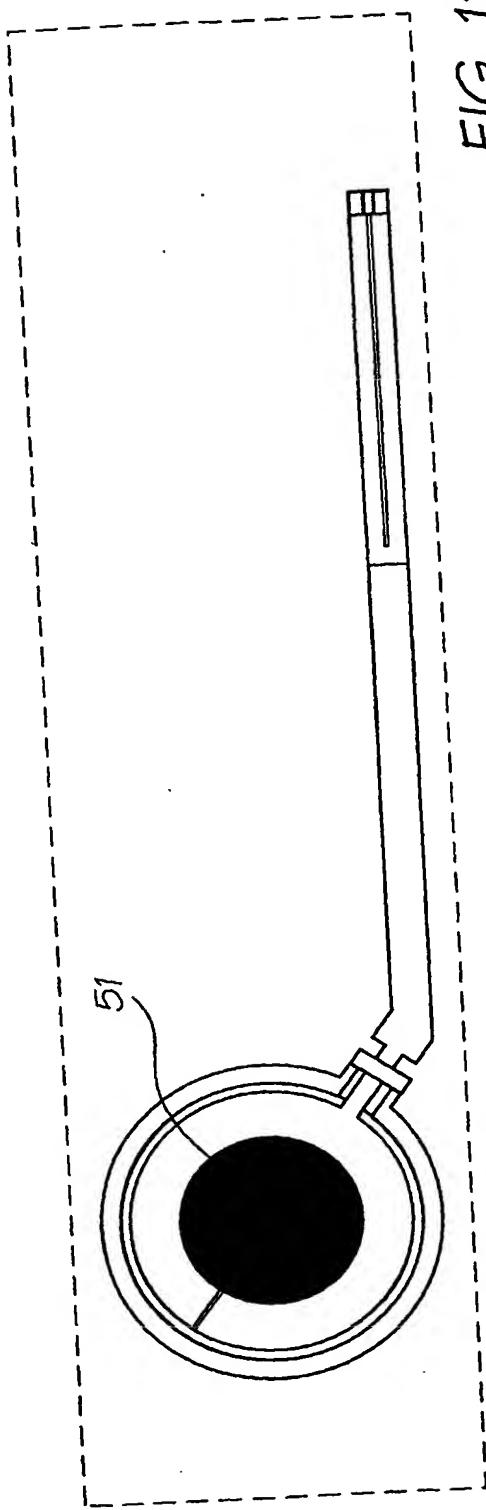


FIG. 12B

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FIG. 13A

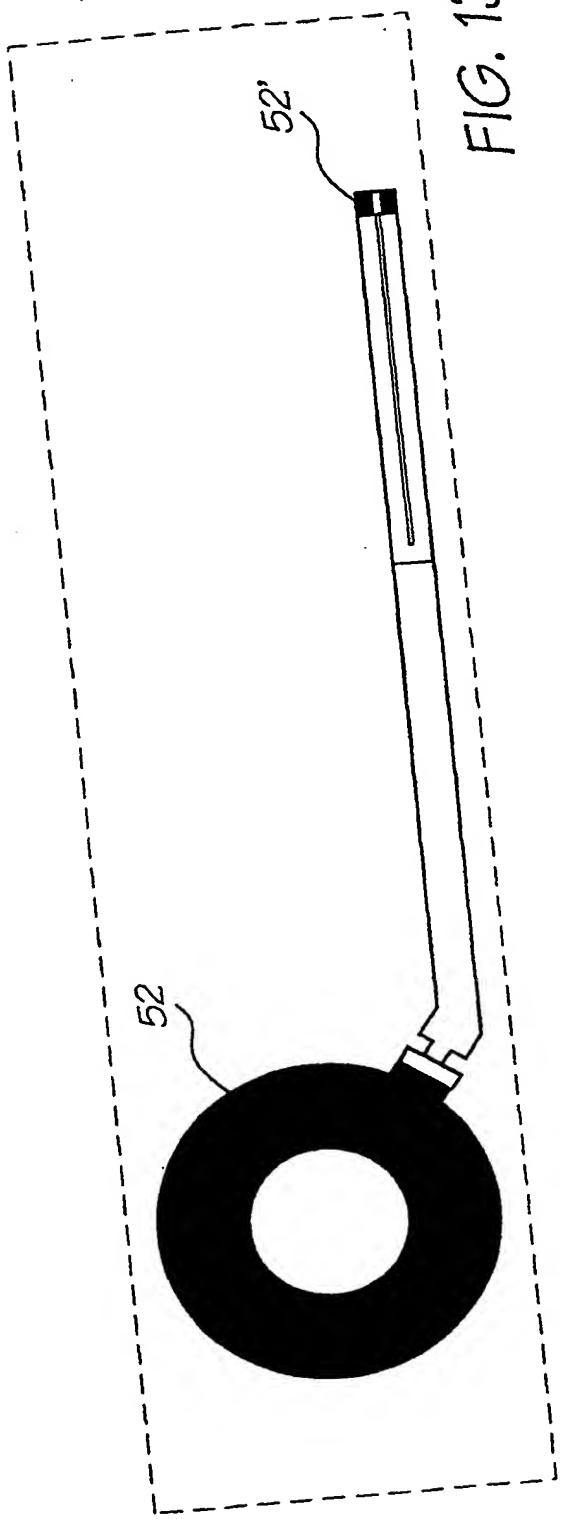
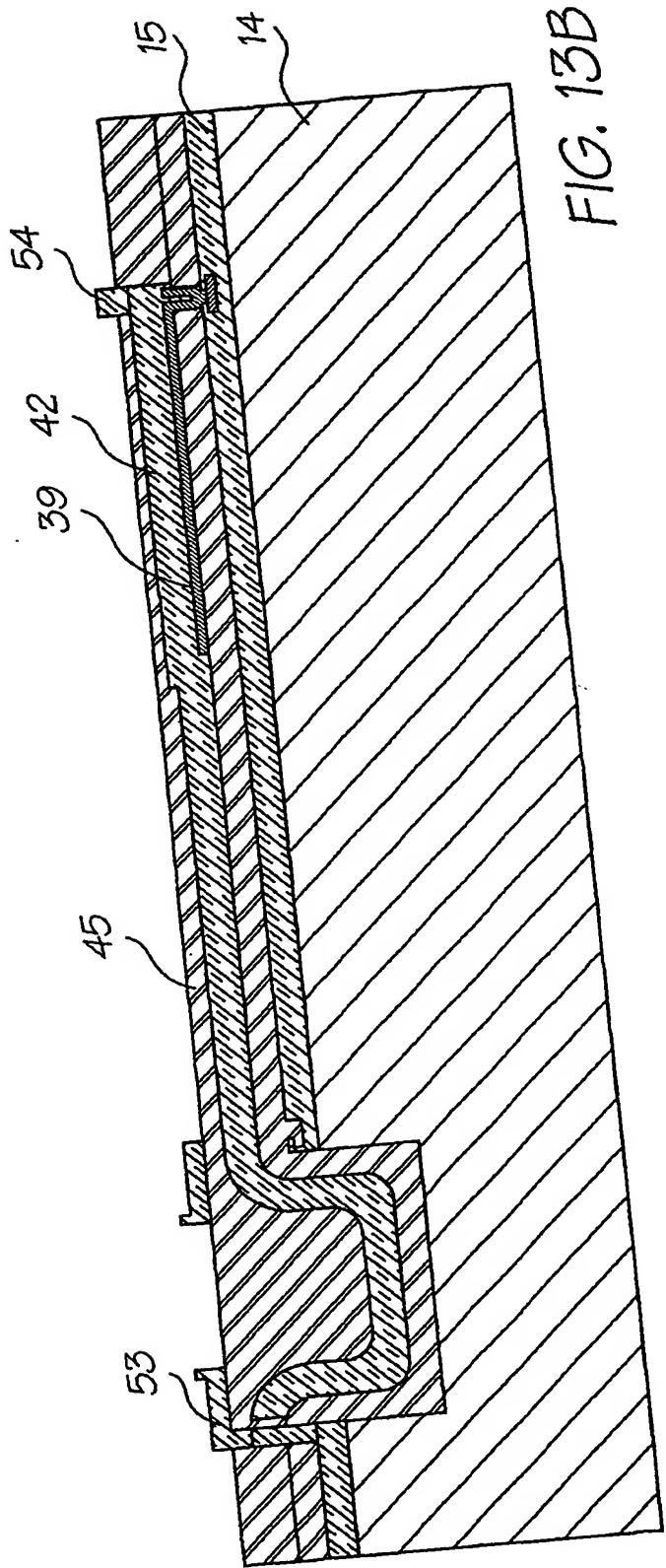
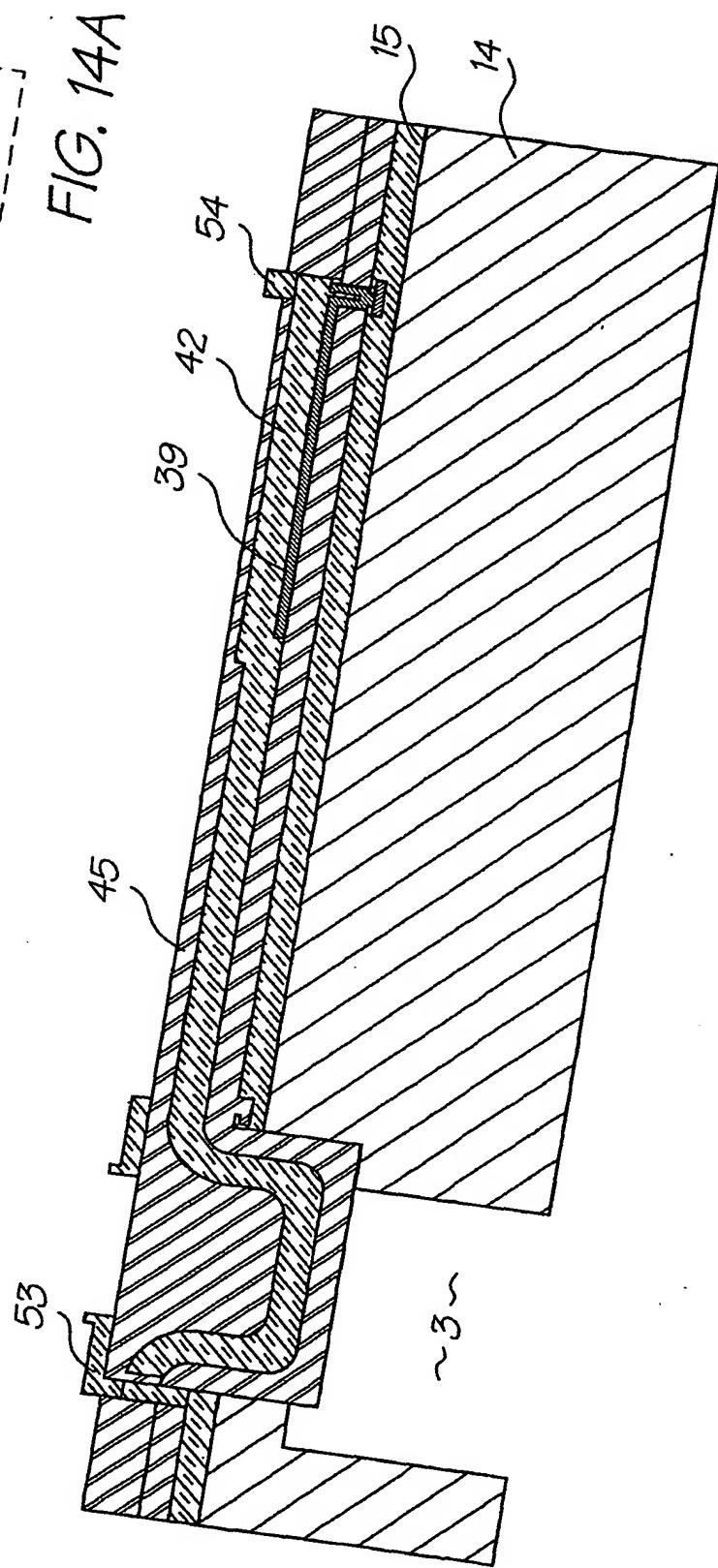
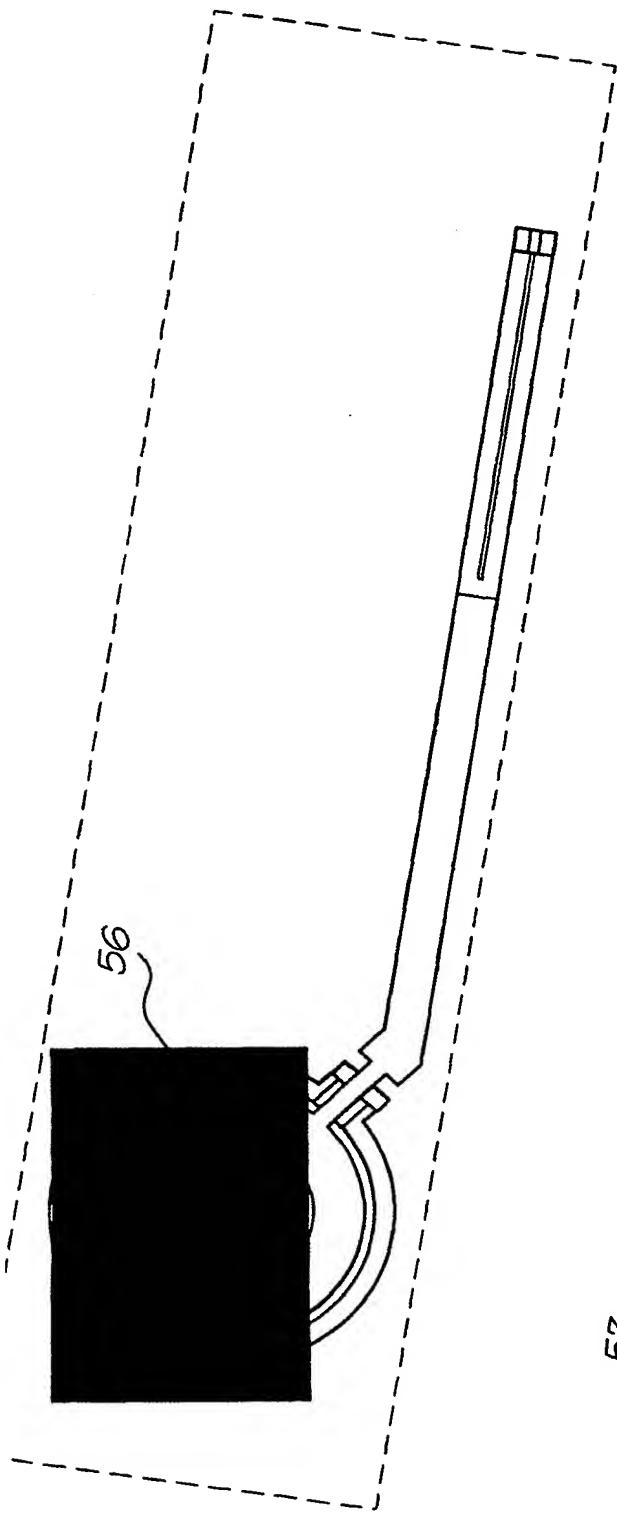


FIG. 13B

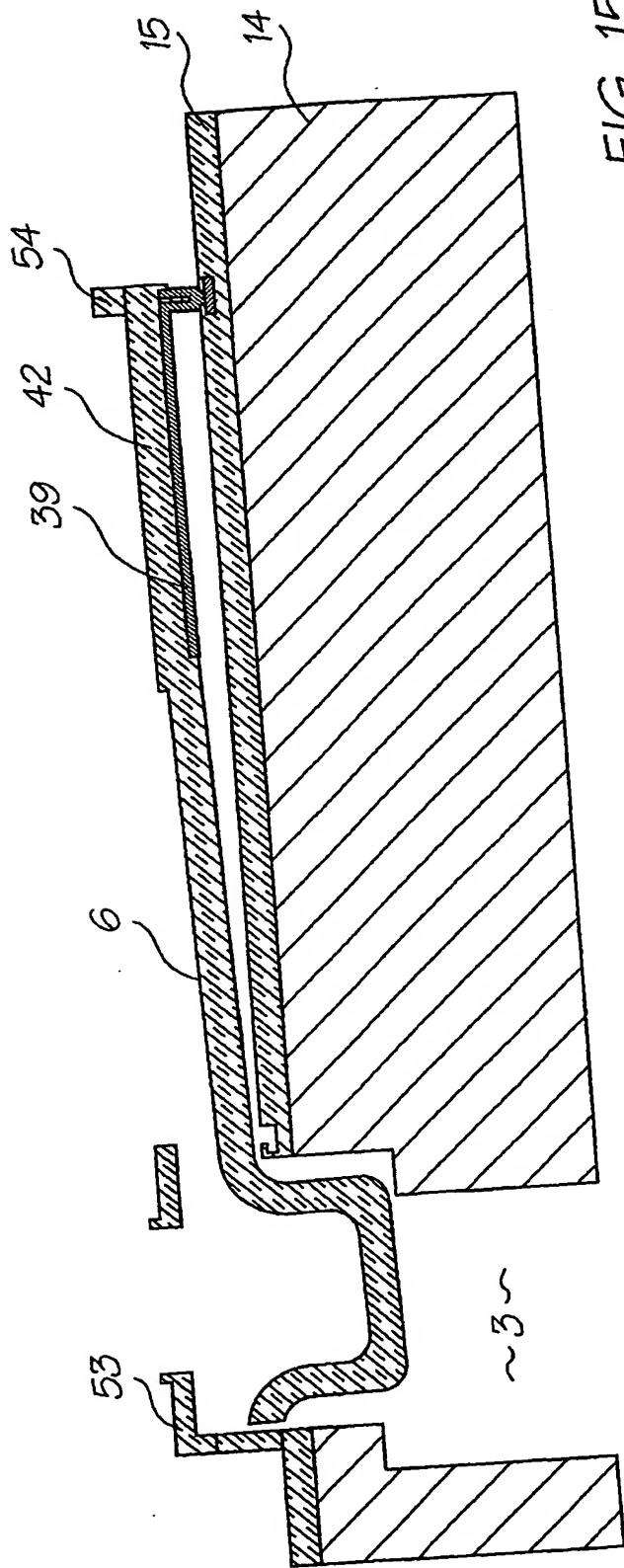


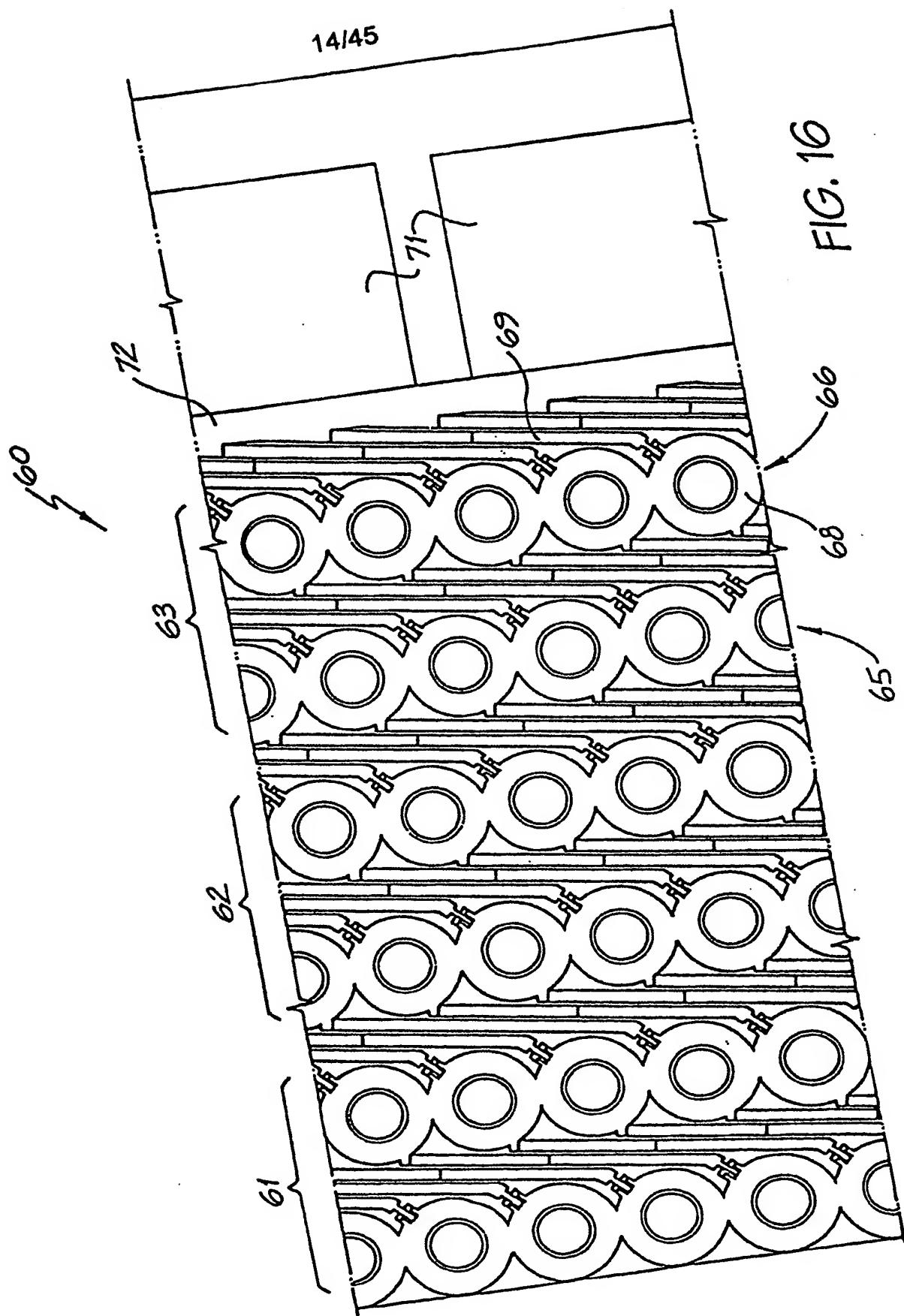
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FIG. 15





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	Silicon		Sacrificial material		Elastomer
	Boron doped silicon		Cupronickel		Polyimide
	Silicon nitride (Si_3N_4)		CoNiFe or NiFe		Indium tin oxide (ITO)
	CMOS device region		Permanent magnet		PTFE
	Aluminum		Polysilicon		Conductive PTFE
	Glass (SiO_2)		Titanium Nitride (TiN)		Terfenol-D
	Copper		Titanium boride (TiB_2)		Shape memory alloy
	Gold		Adhesive		Tantalum
			Resist		Ink

FIG. 17

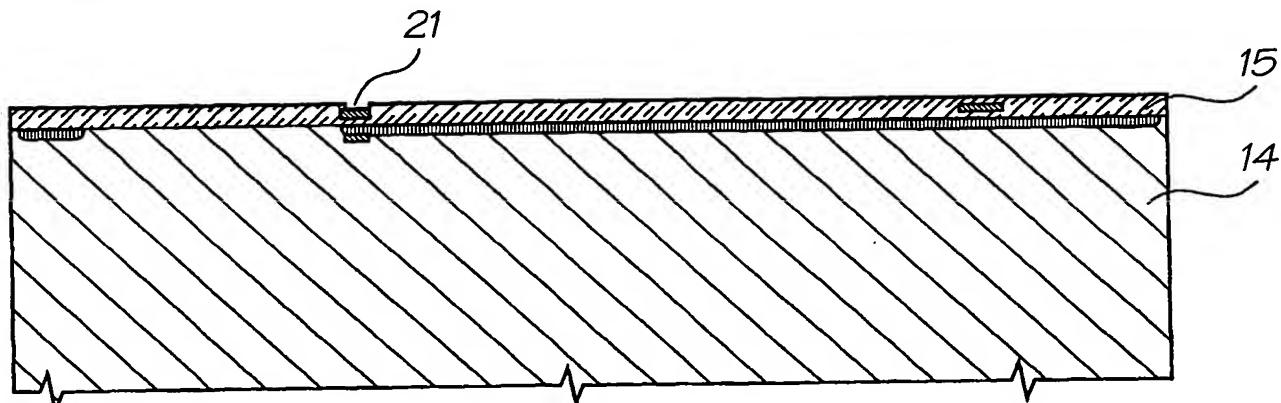


FIG. 18

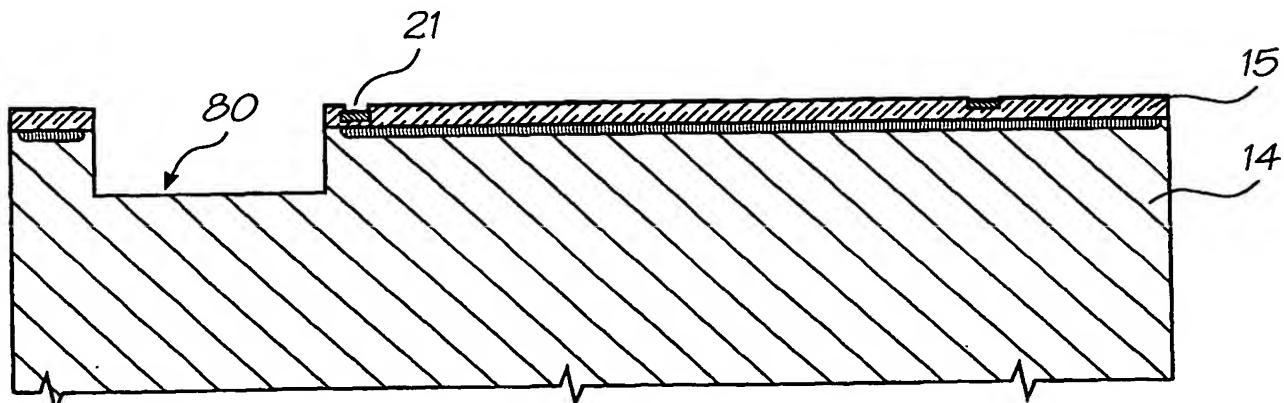


FIG. 19

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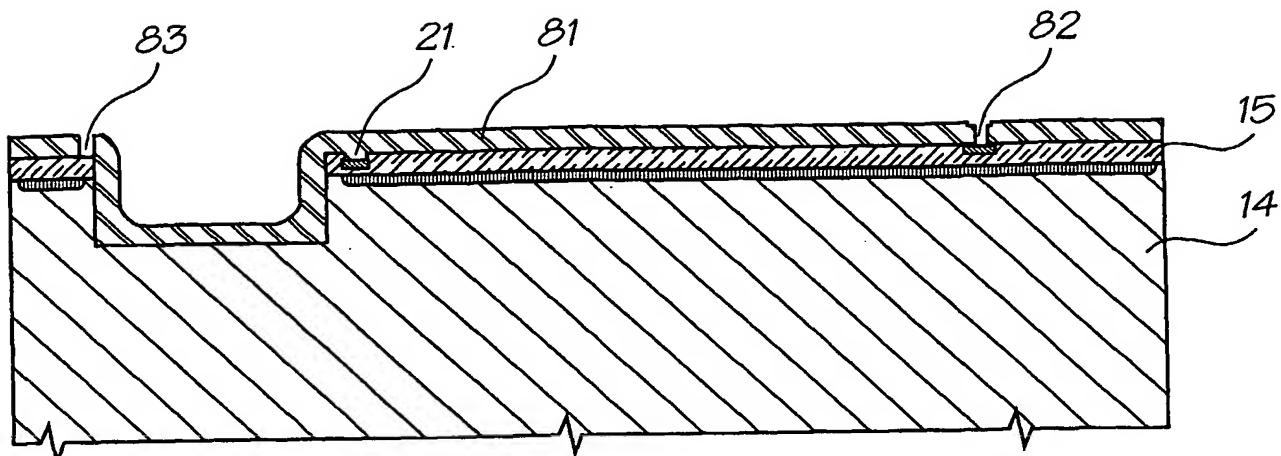


FIG. 20

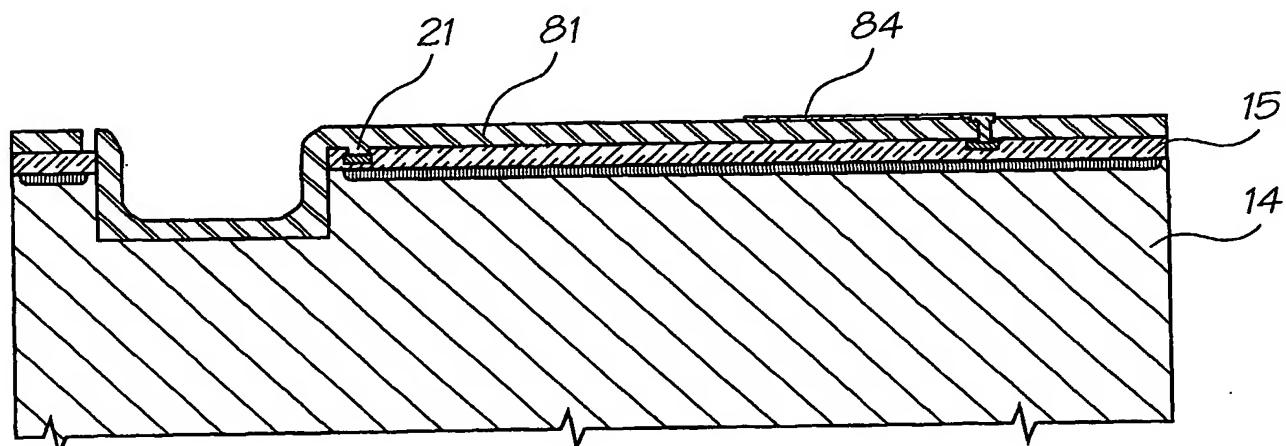


FIG. 21

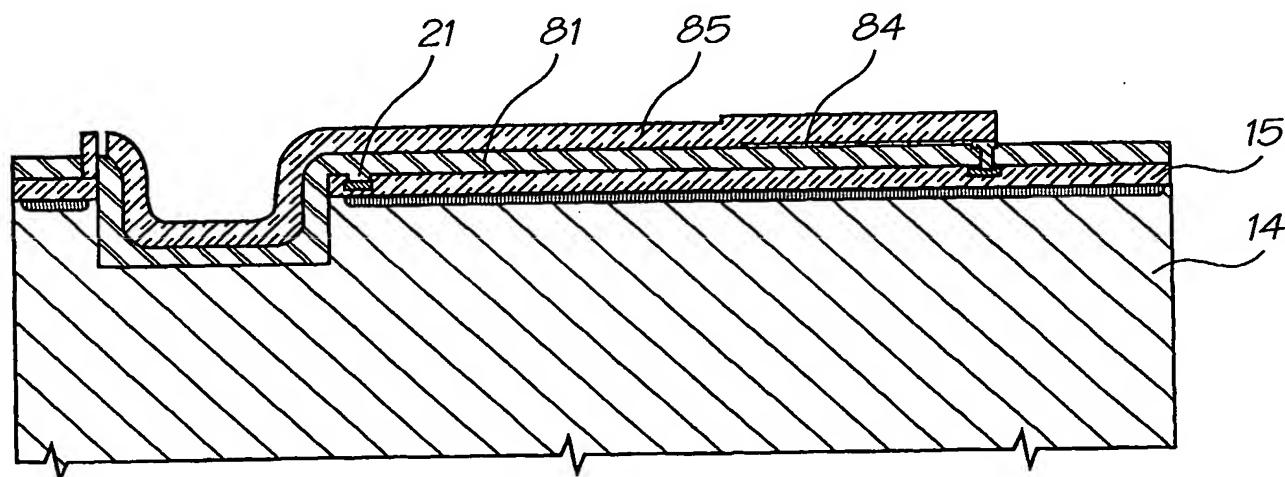


FIG. 22

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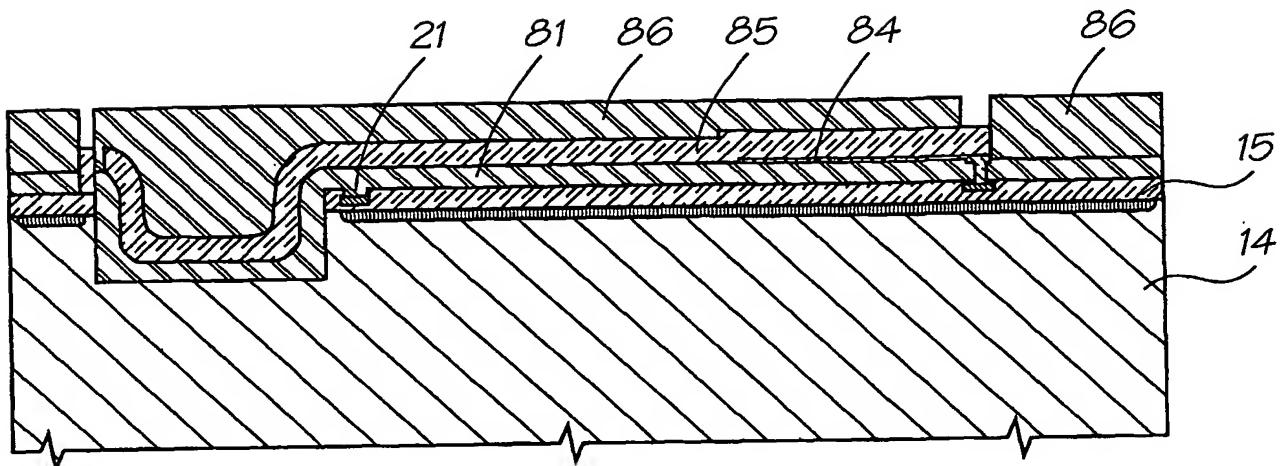


FIG. 23

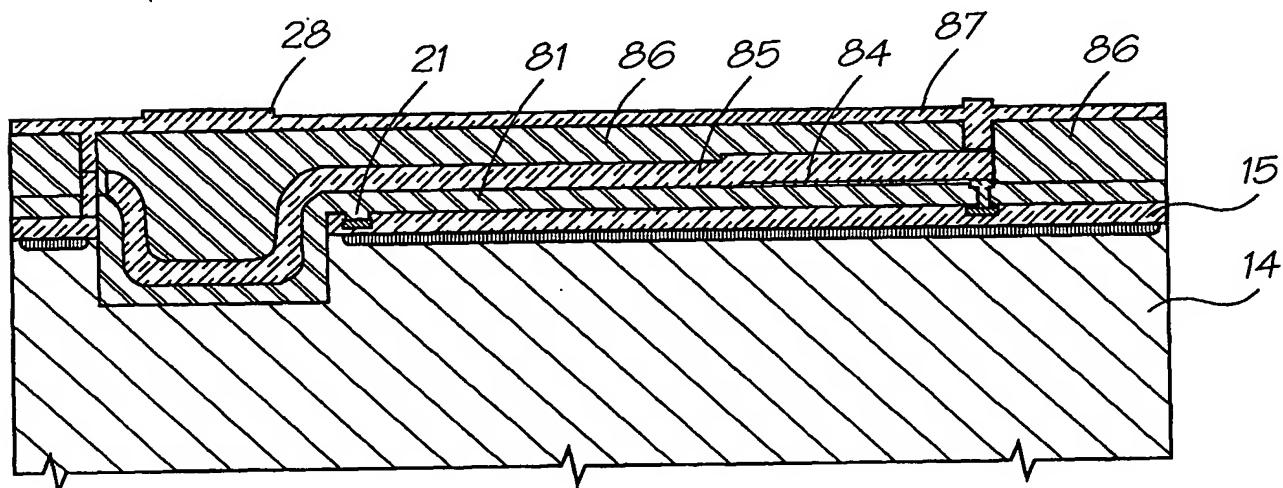


FIG. 24

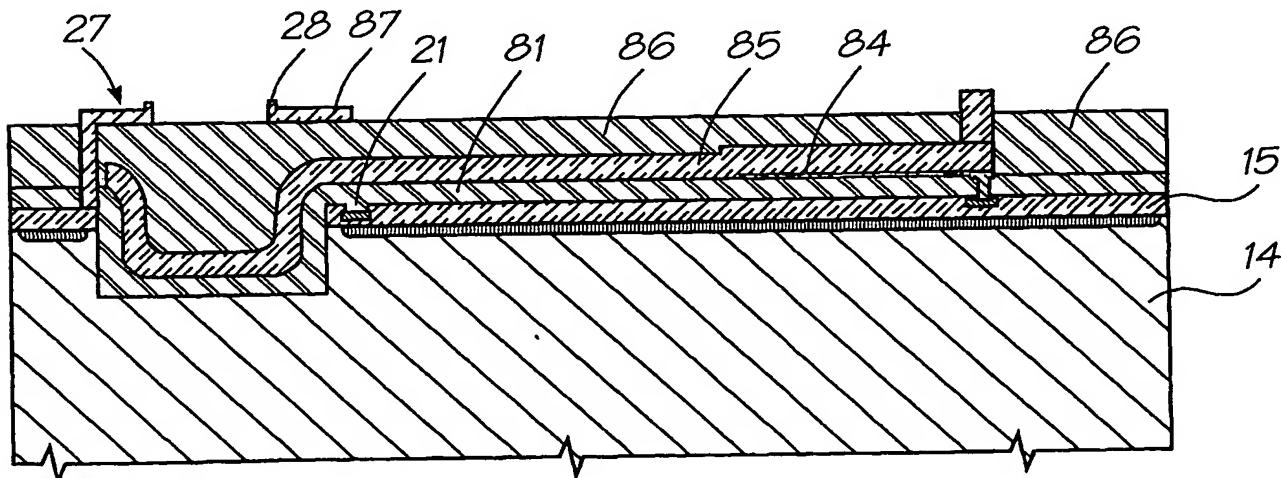


FIG. 25

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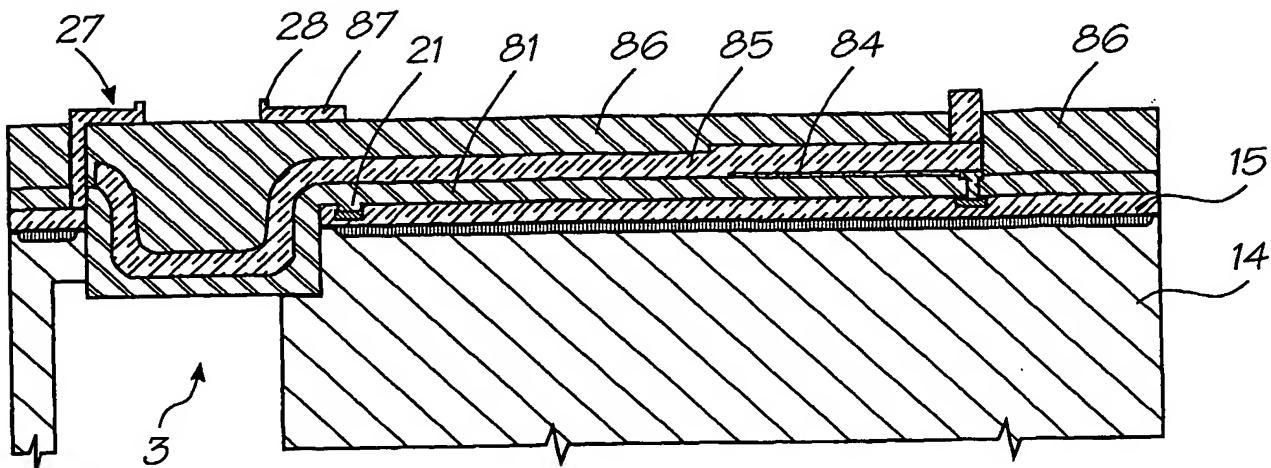


FIG. 26

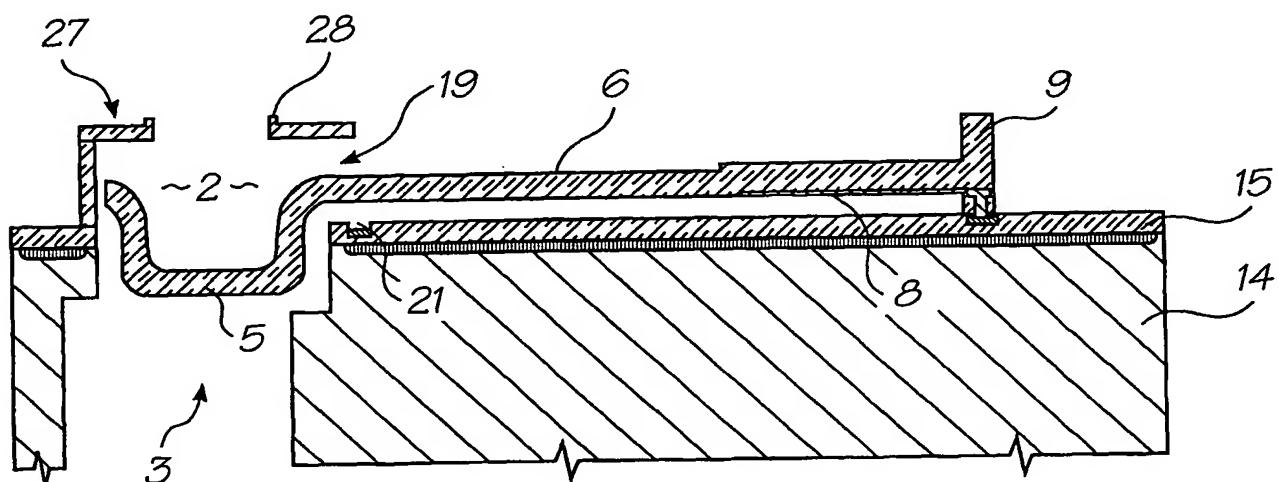


FIG. 27

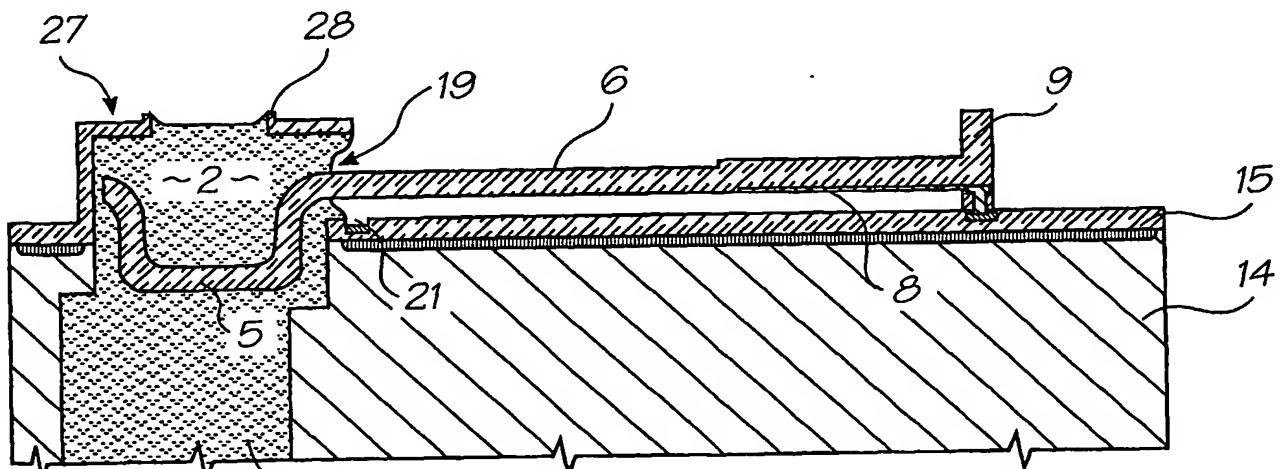


FIG. 28

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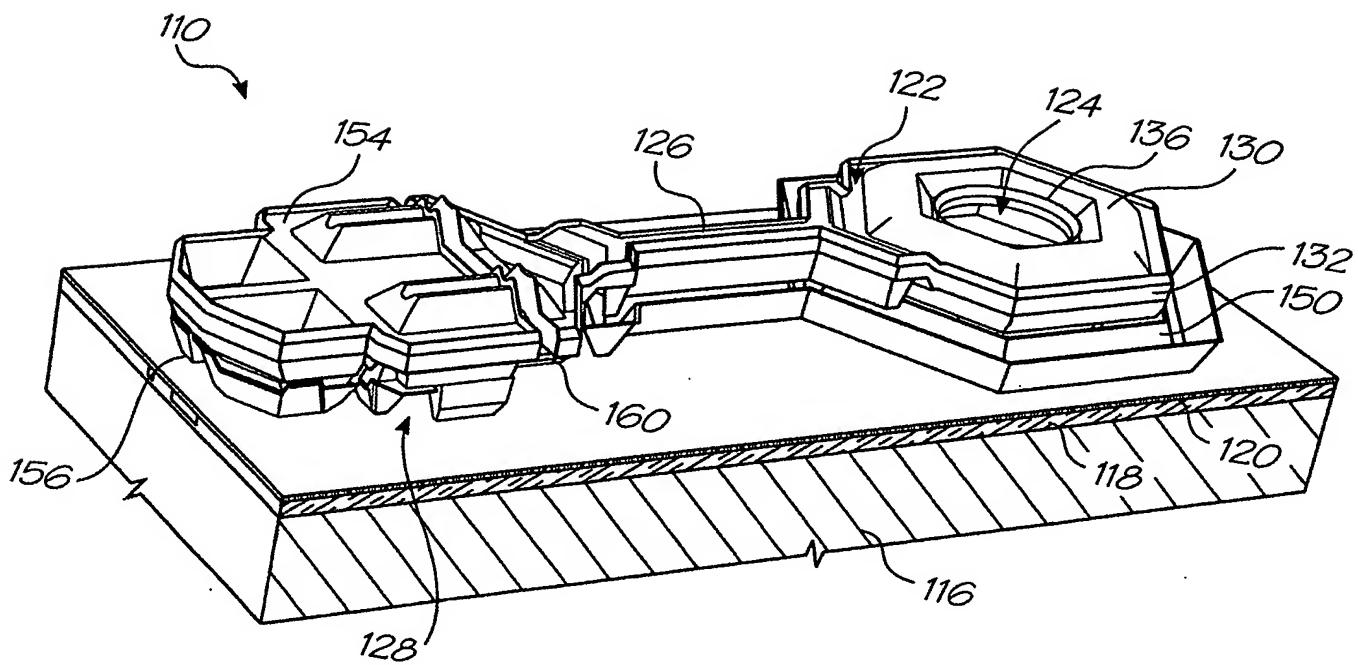


FIG. 29

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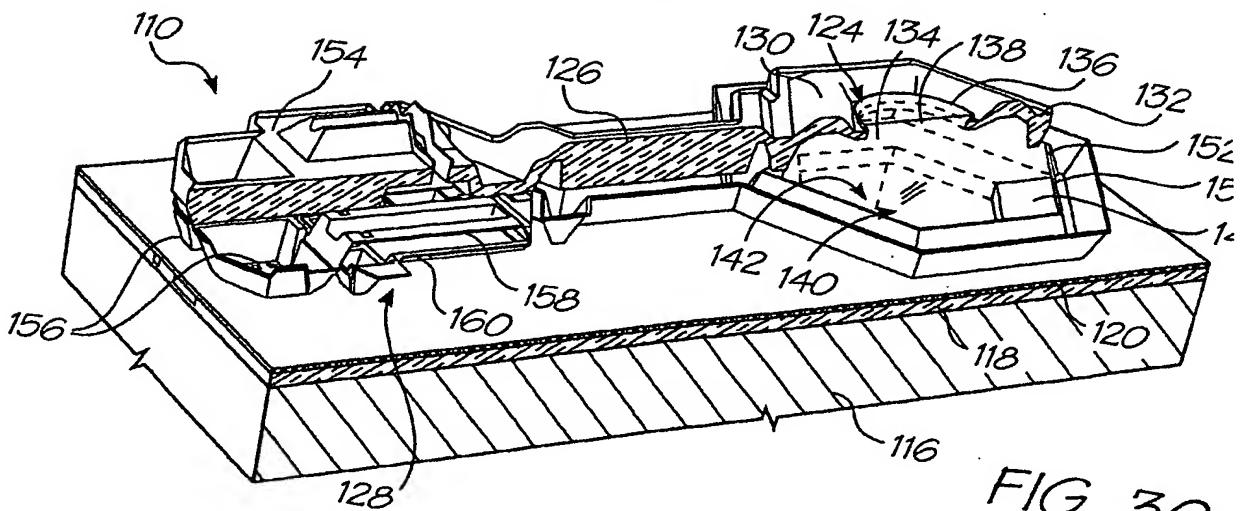


FIG. 30

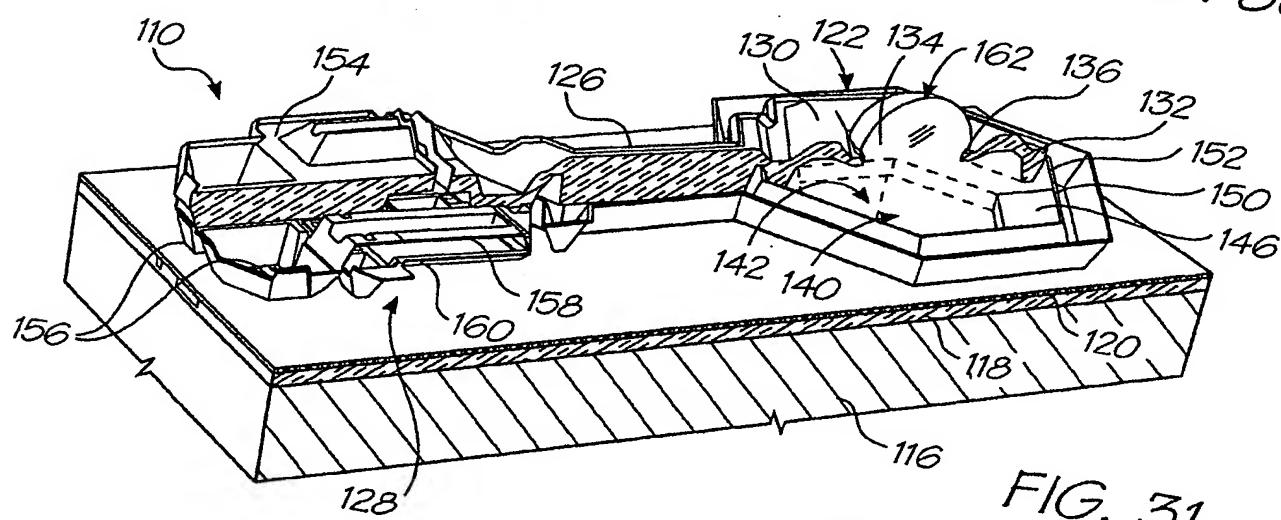


FIG. 31

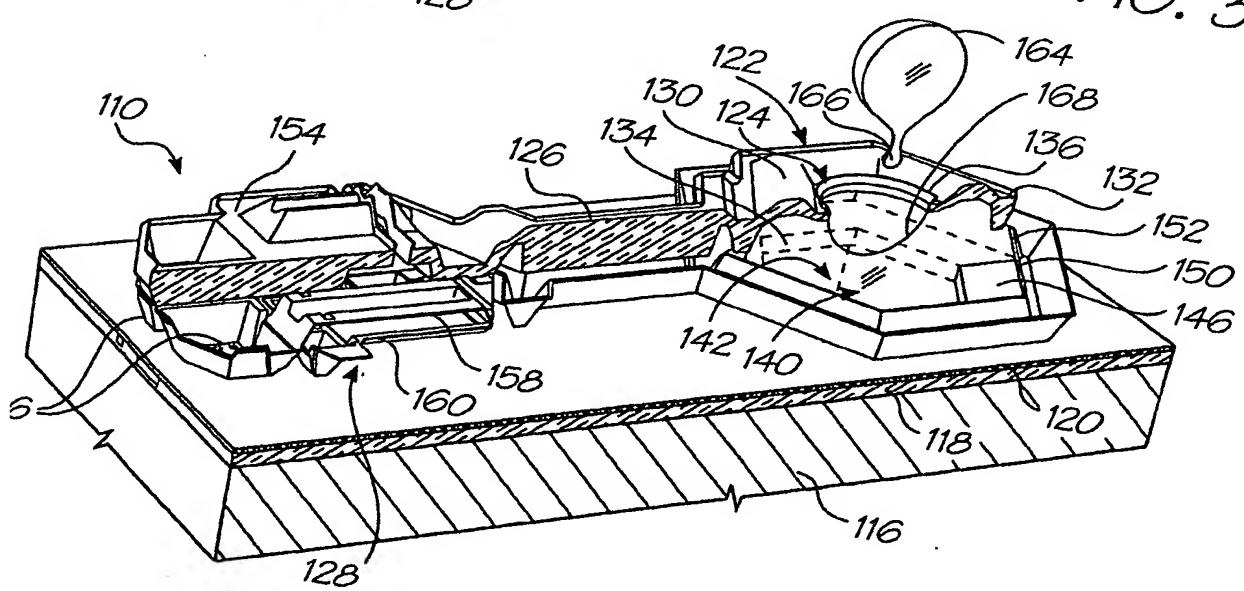


FIG. 32

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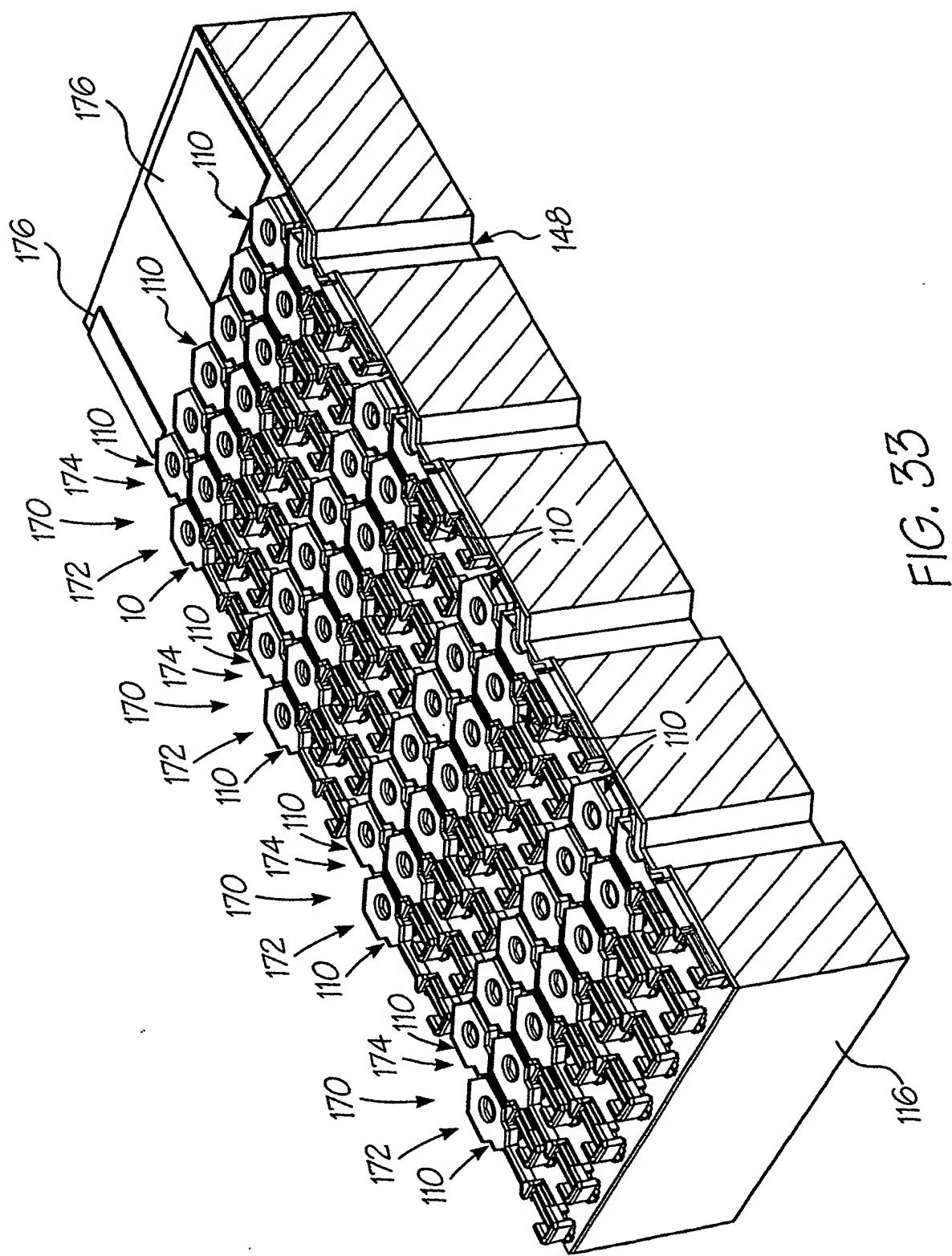


FIG. 33

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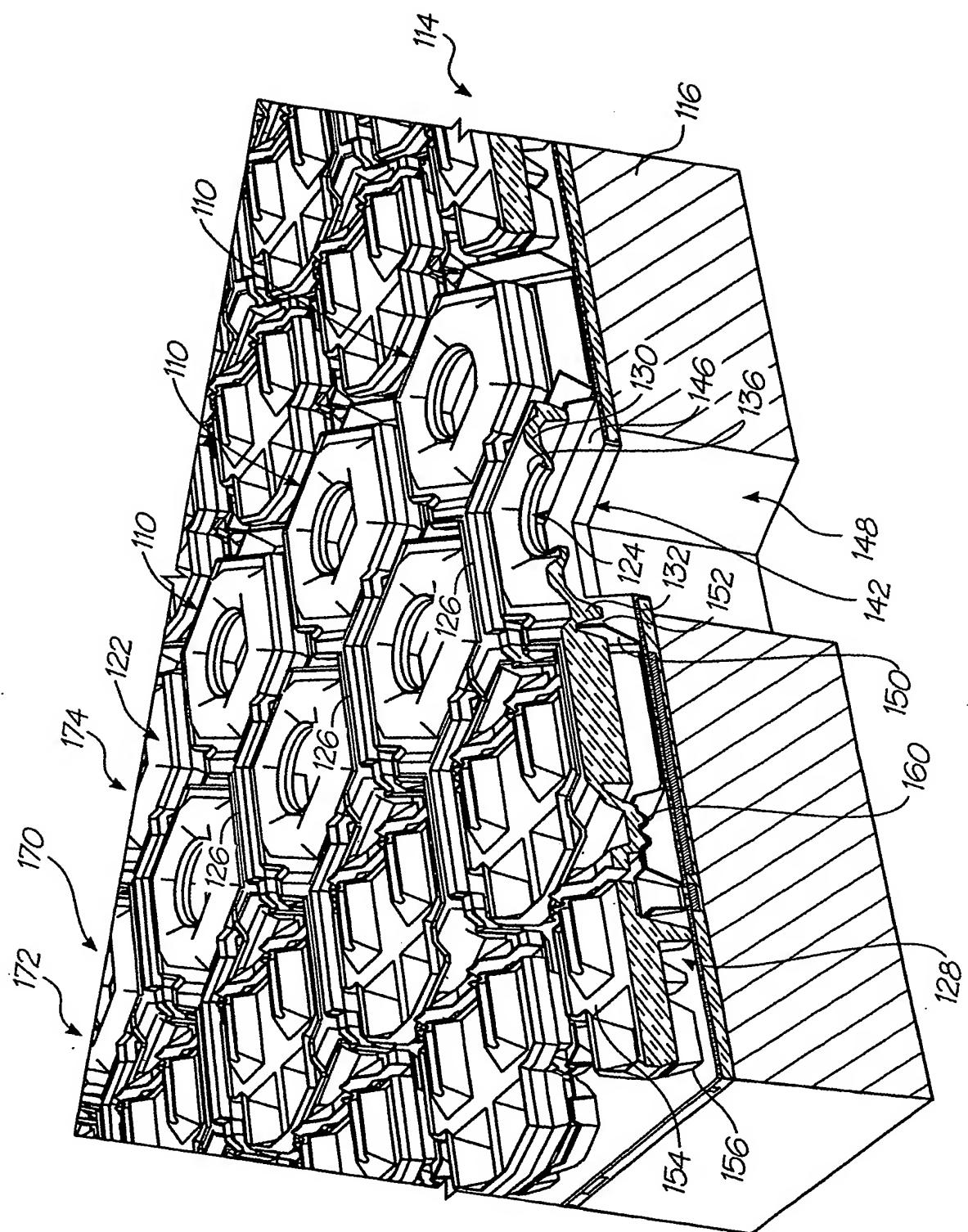
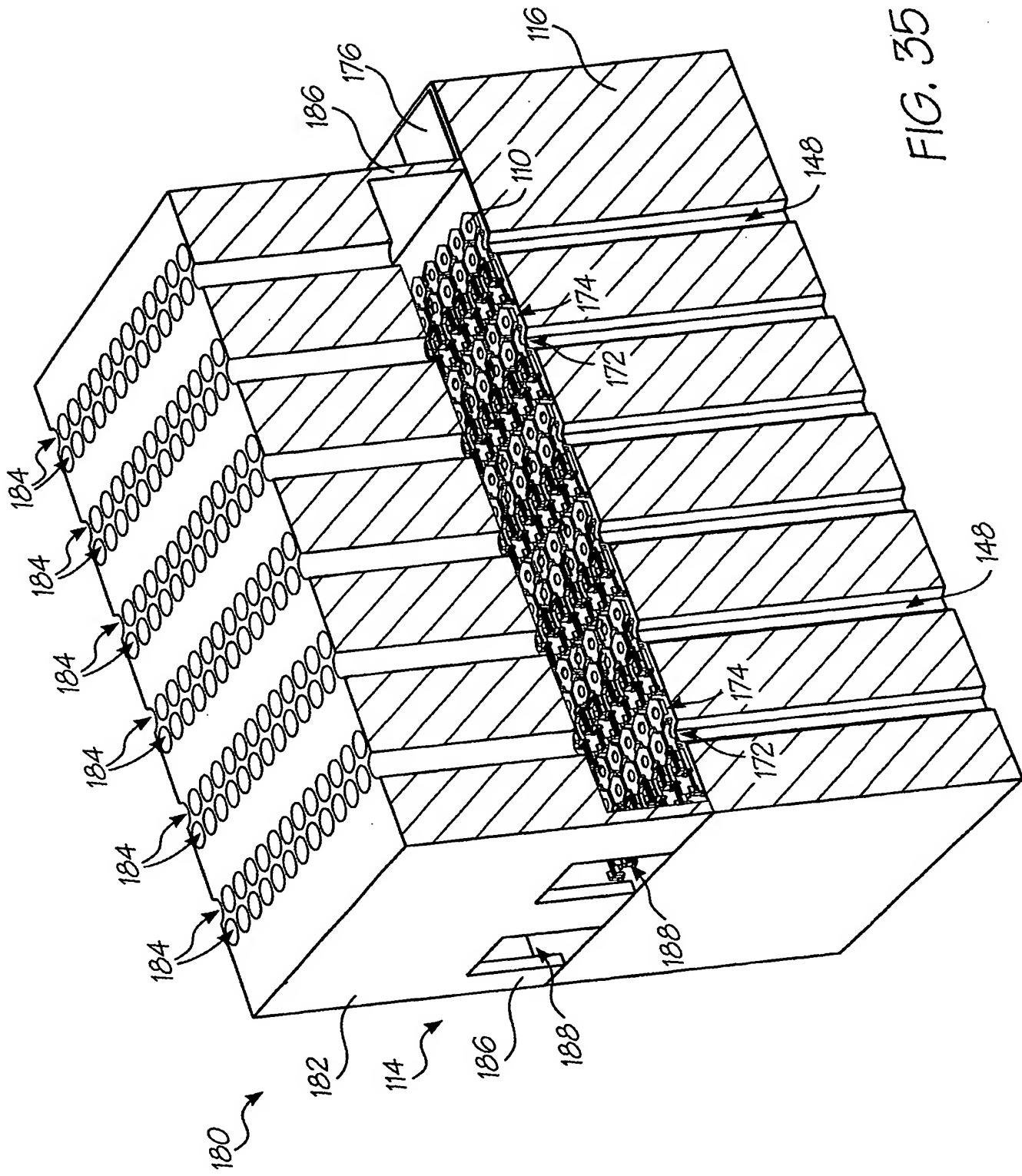


FIG. 34

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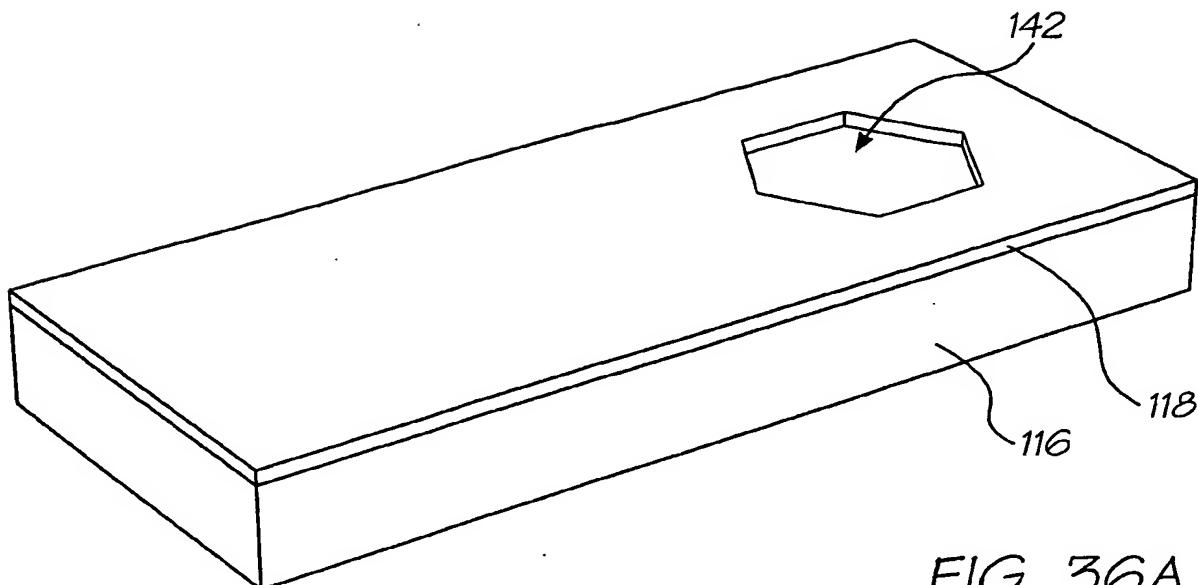


FIG. 36A

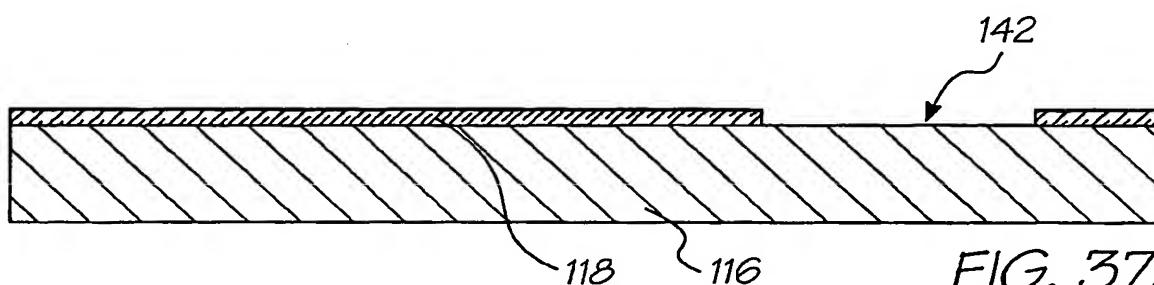


FIG. 37A

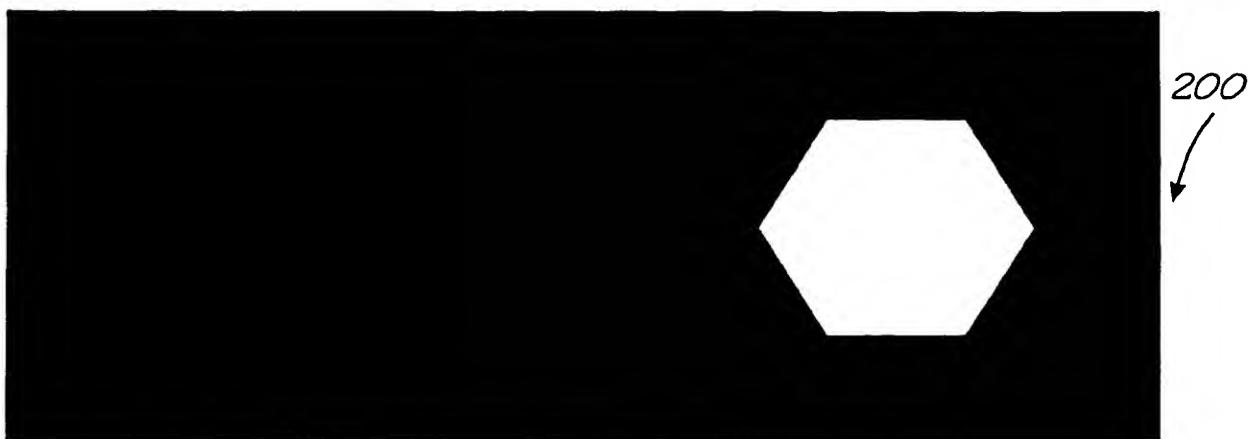


FIG. 38A

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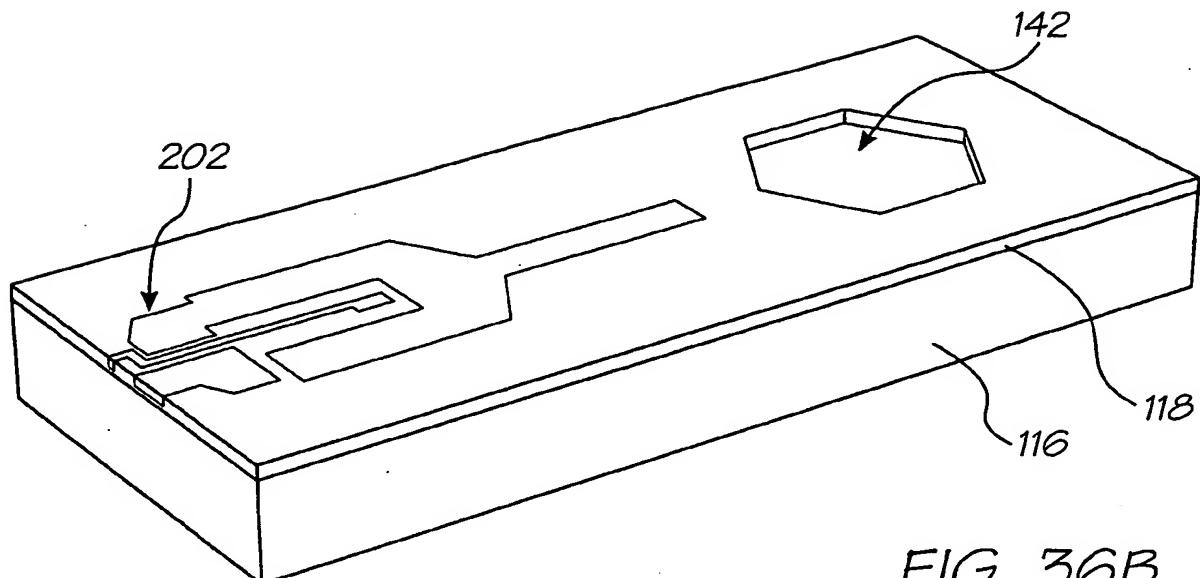


FIG. 36B

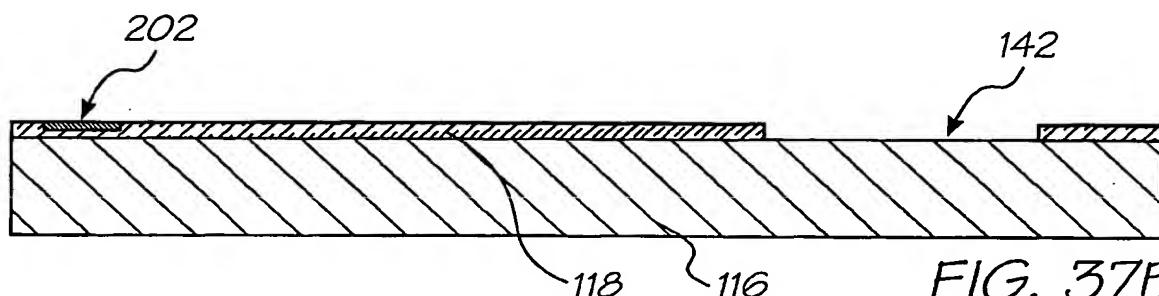


FIG. 37B

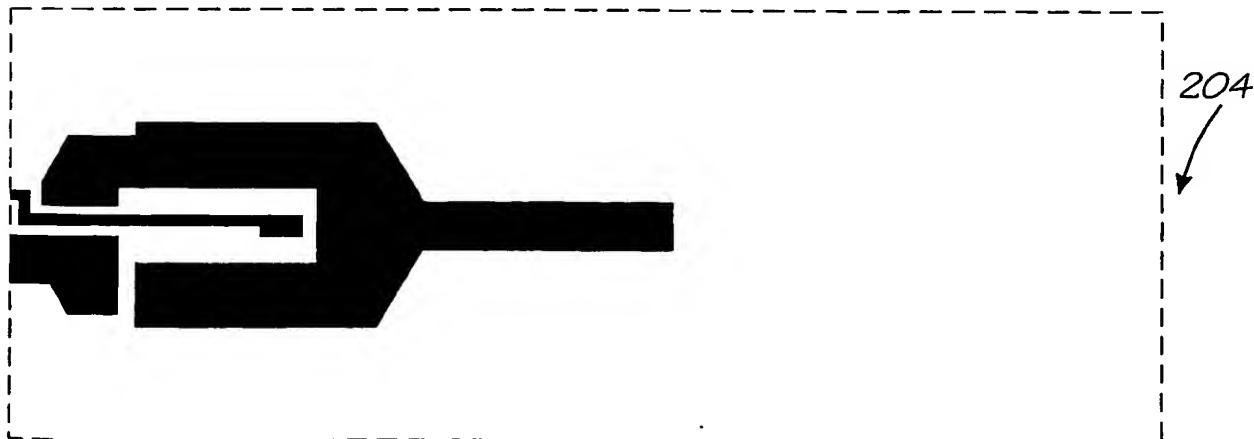


FIG. 38B

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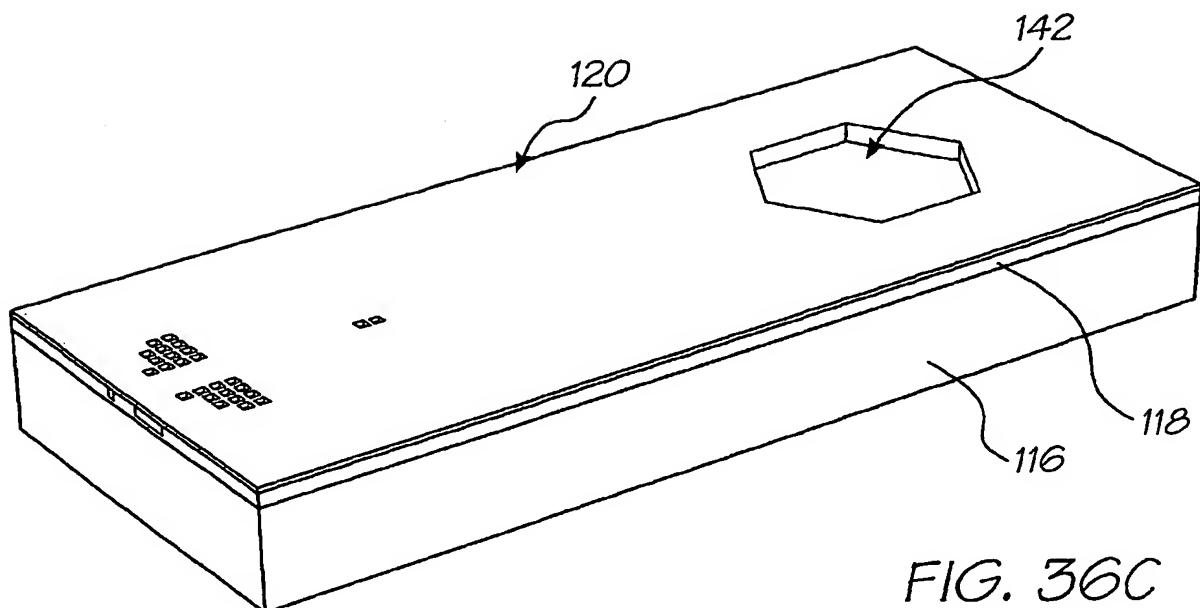


FIG. 36C

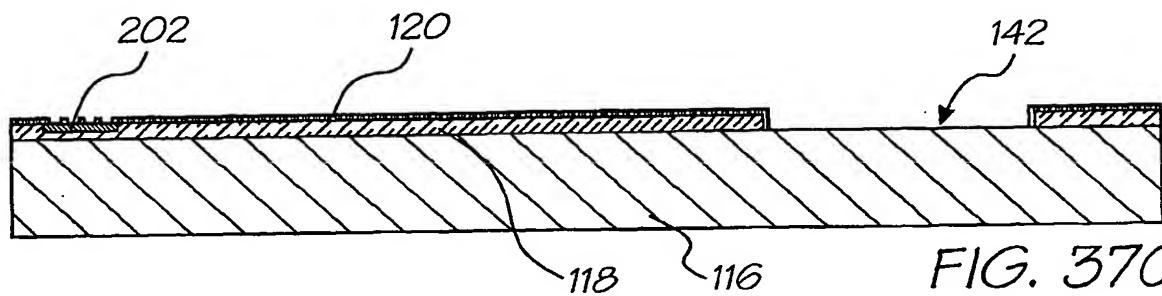


FIG. 37C

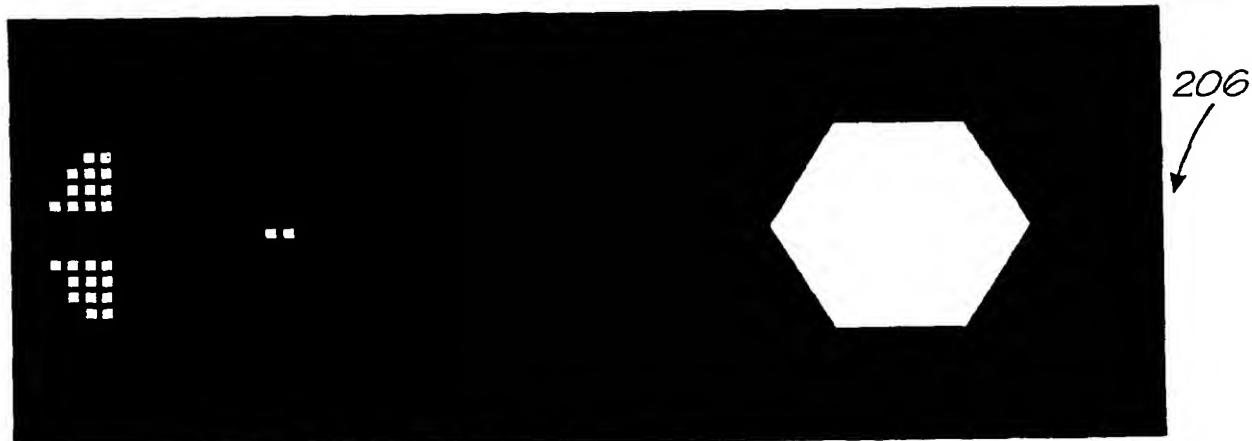


FIG. 38C

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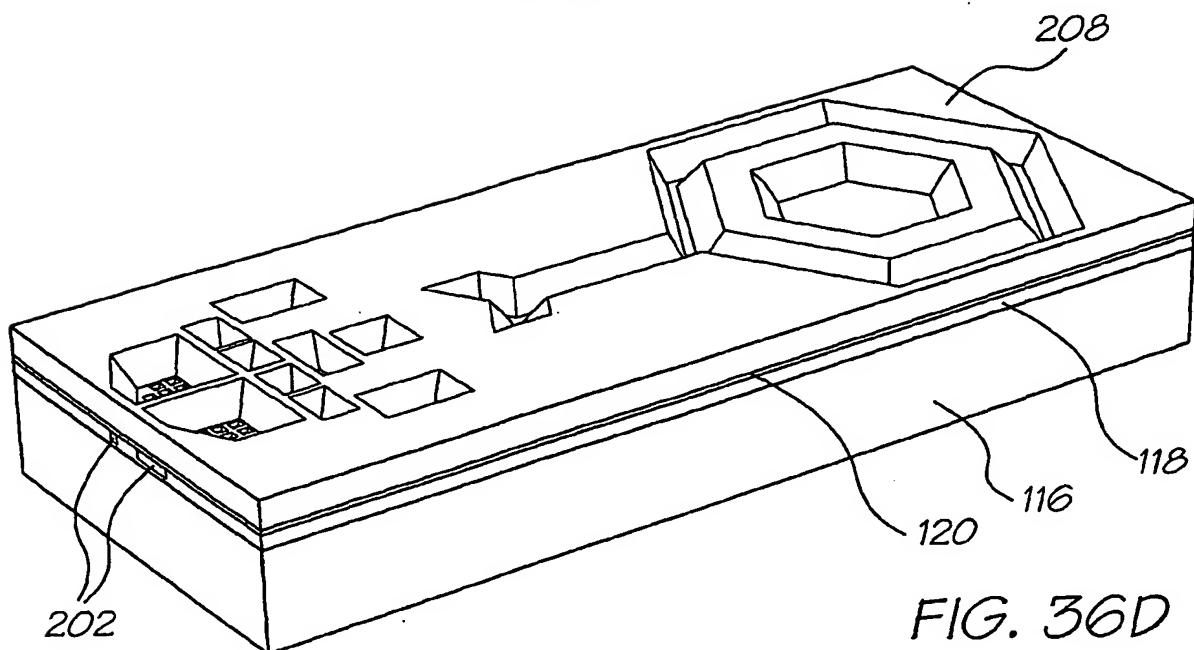


FIG. 36D

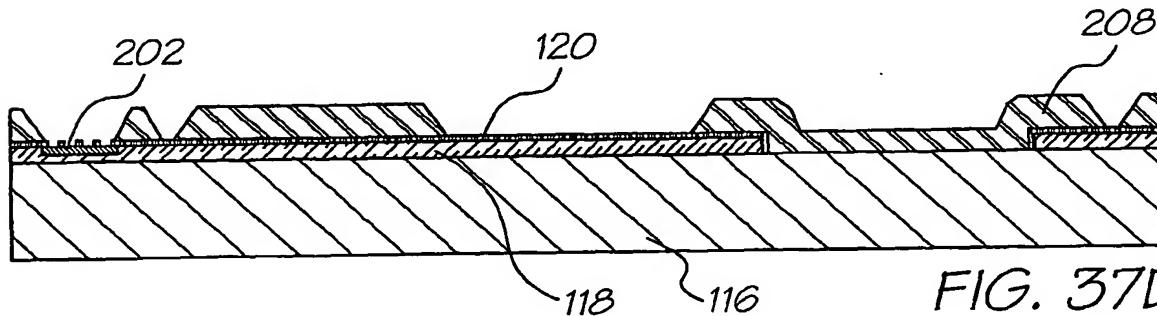


FIG. 37D

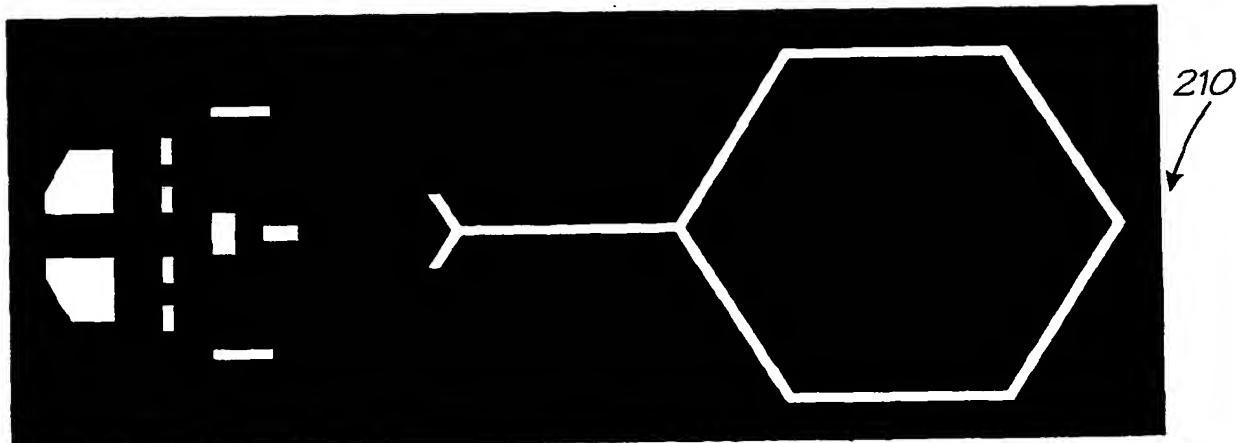
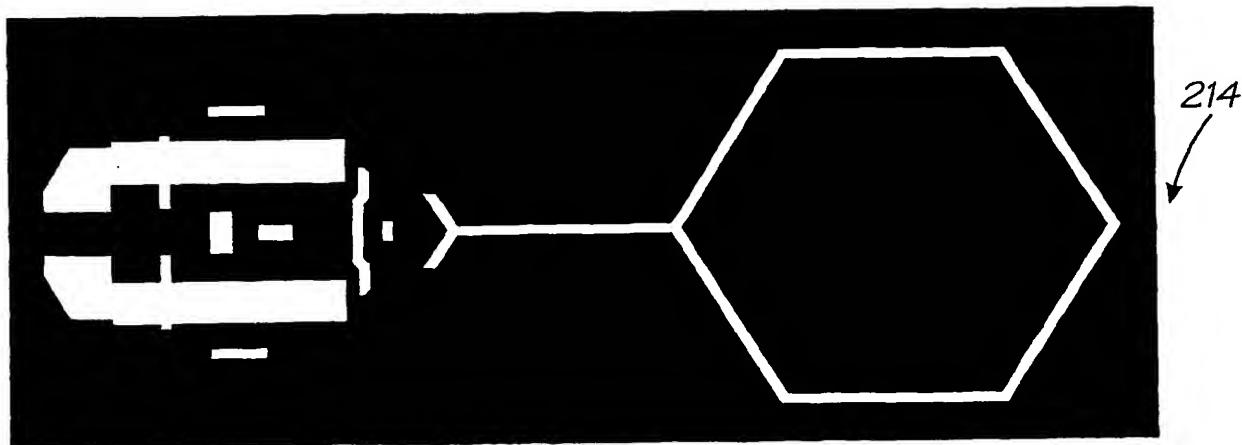
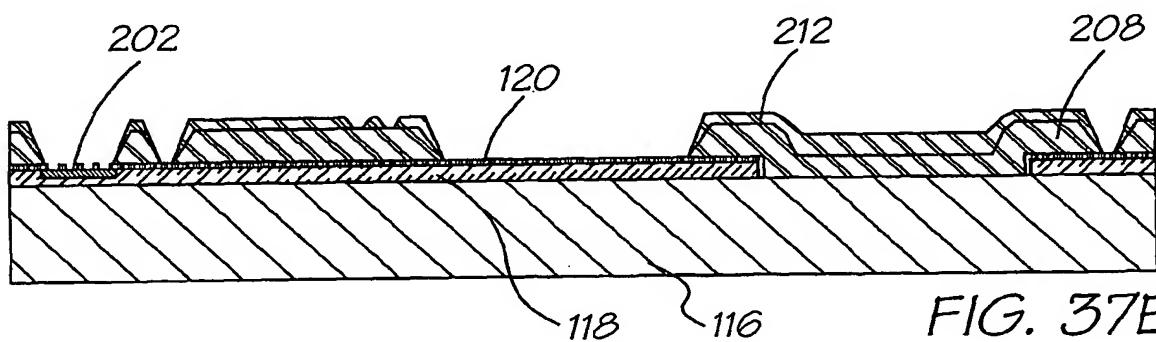
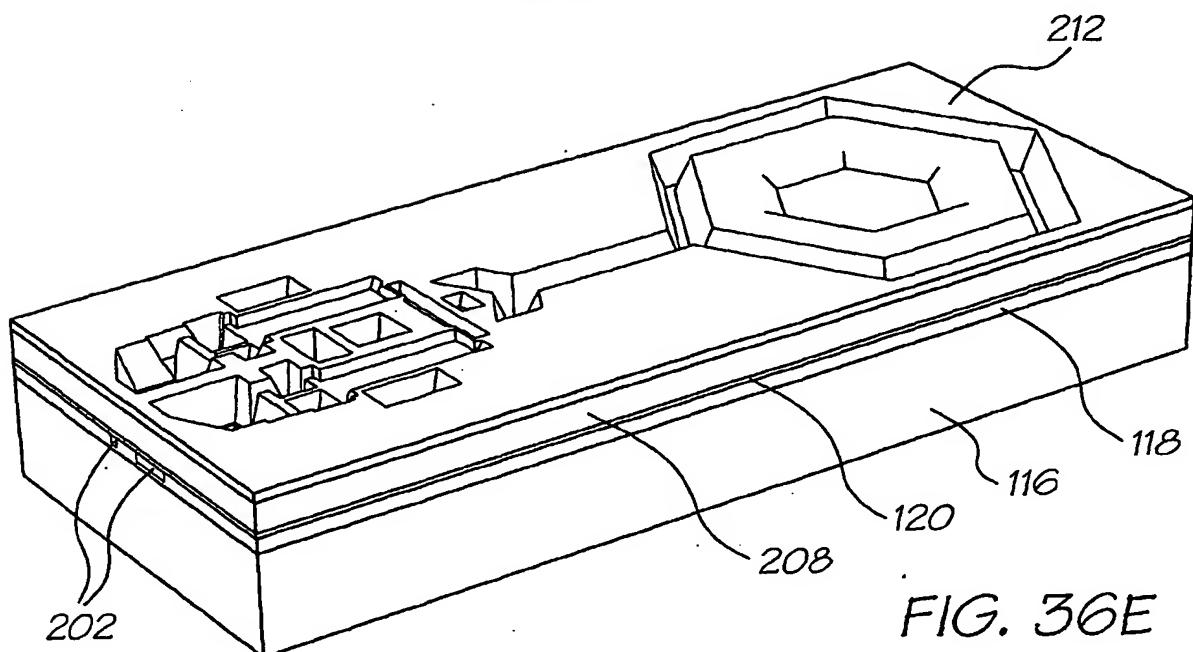
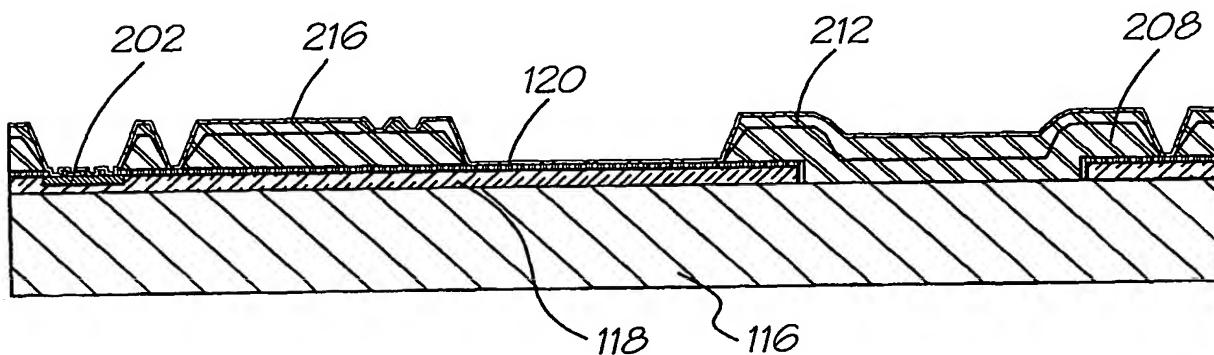
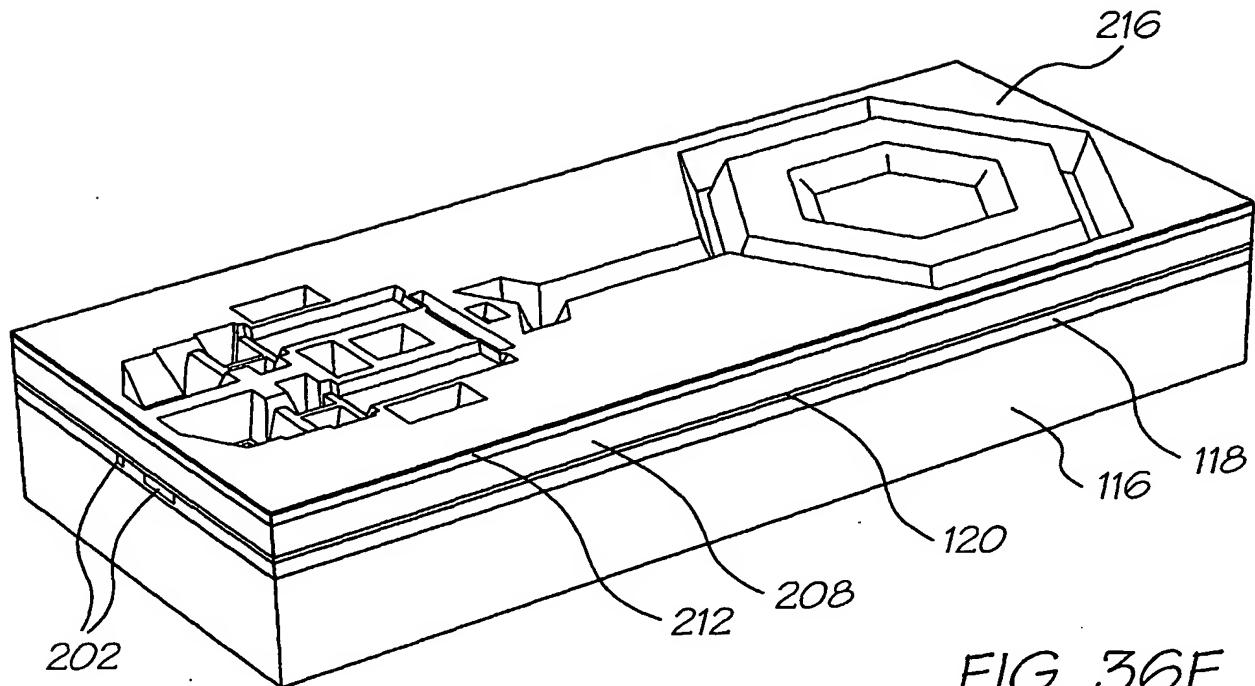


FIG. 38D

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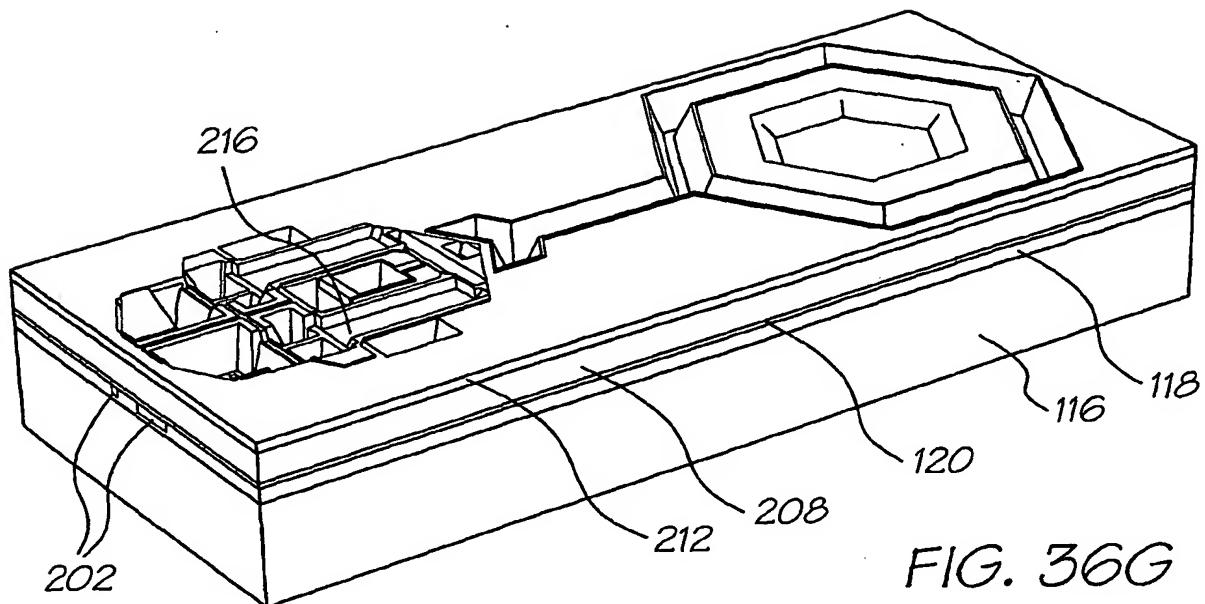


FIG. 36G

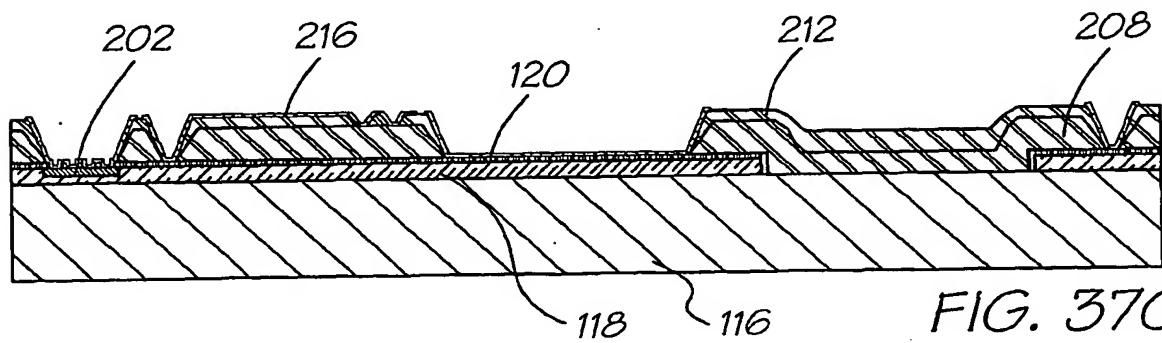


FIG. 37G

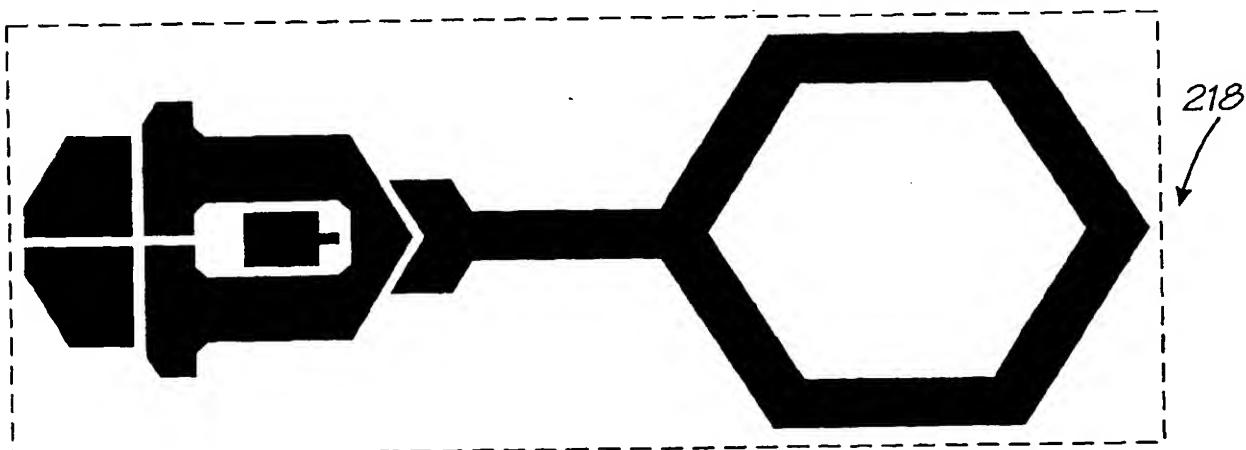


FIG. 38F

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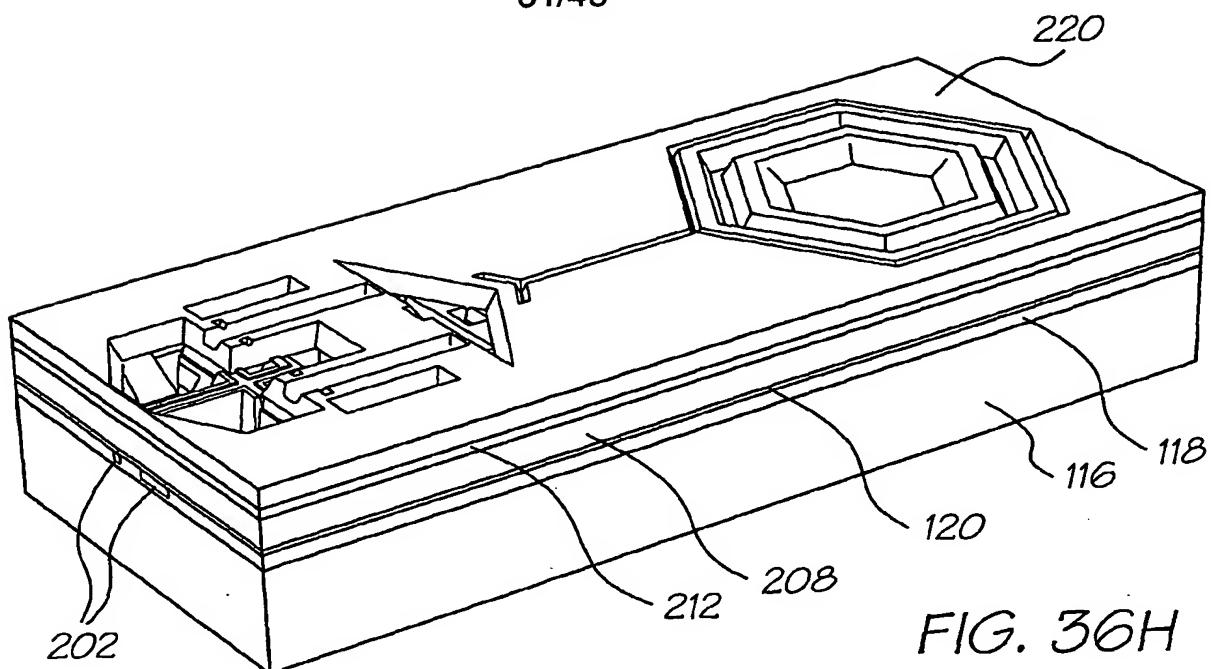


FIG. 36H

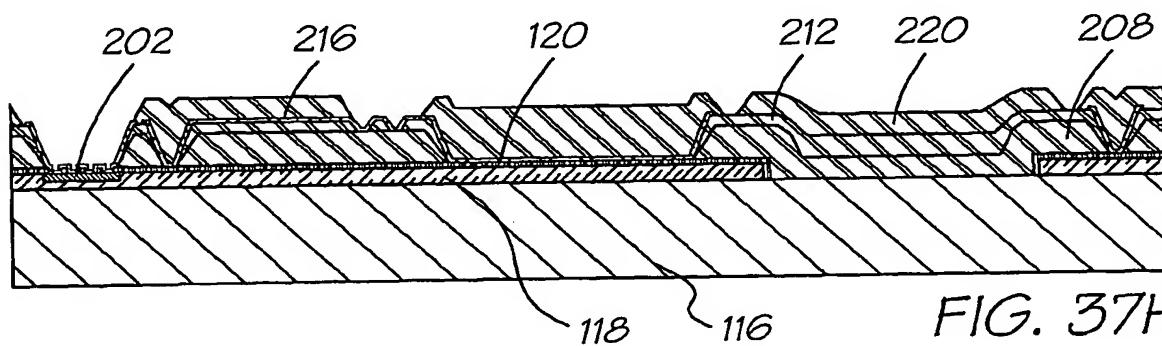


FIG. 37H

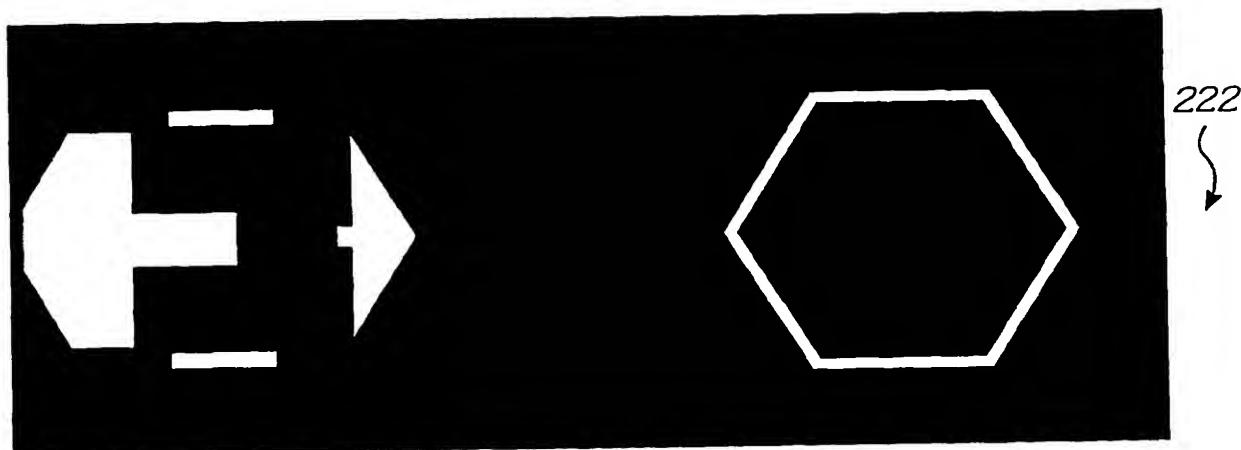


FIG. 38G

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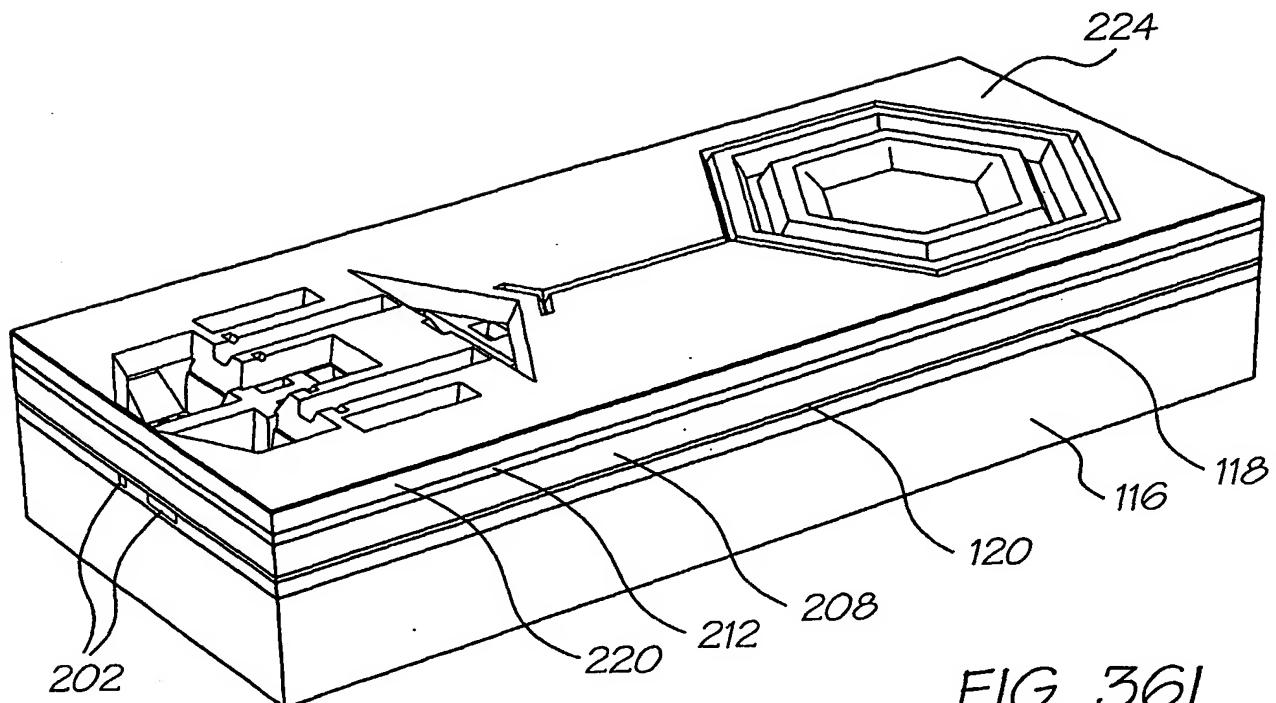


FIG. 361

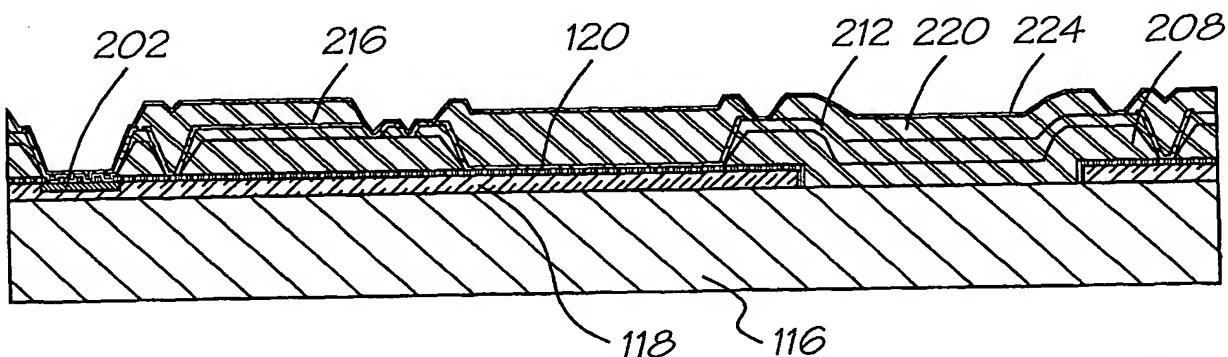


FIG. 371

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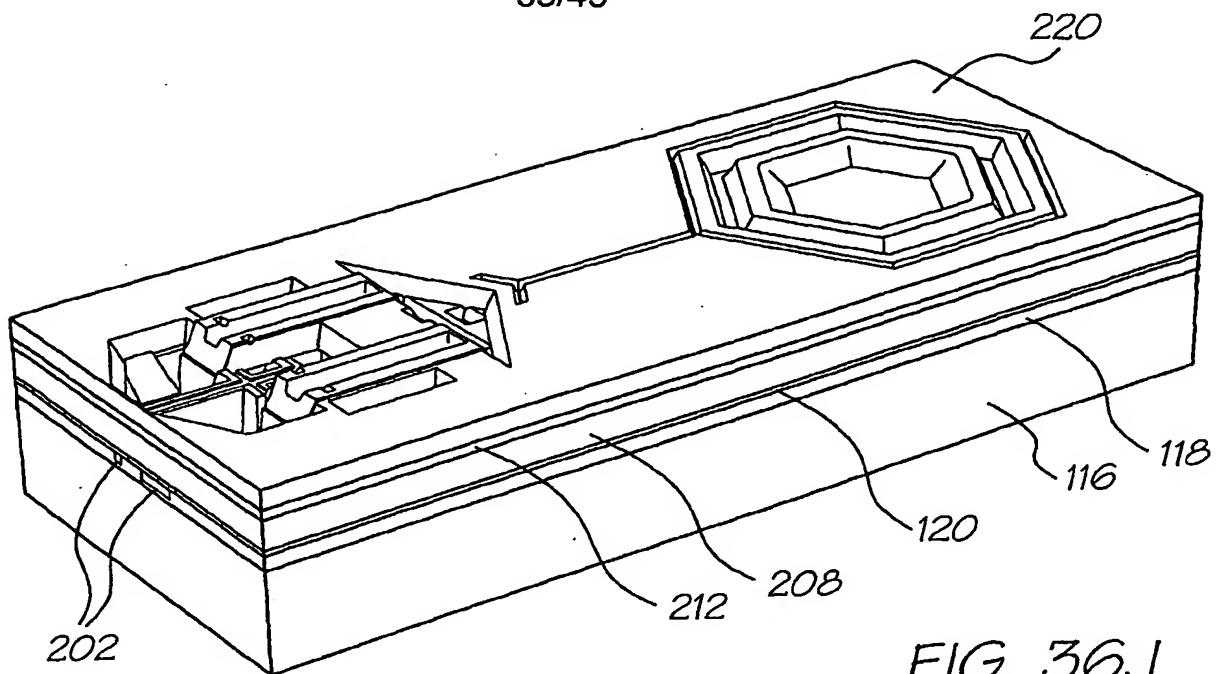


FIG. 36J

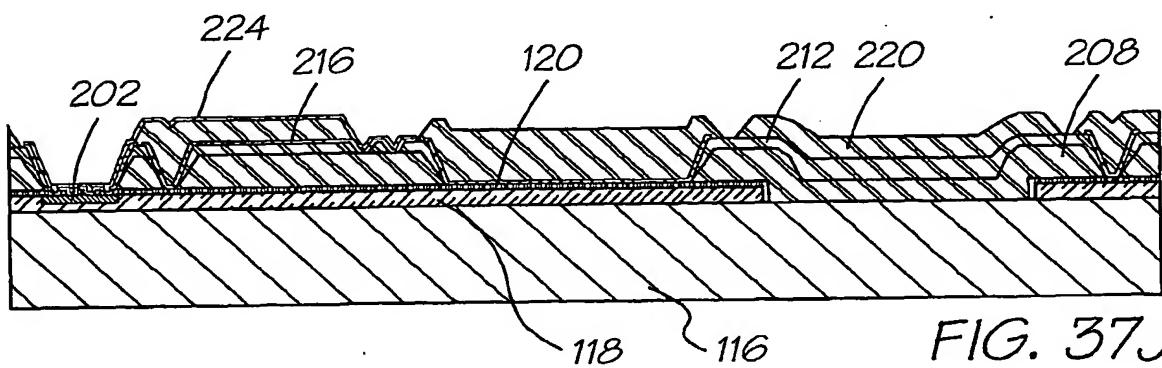


FIG. 37J

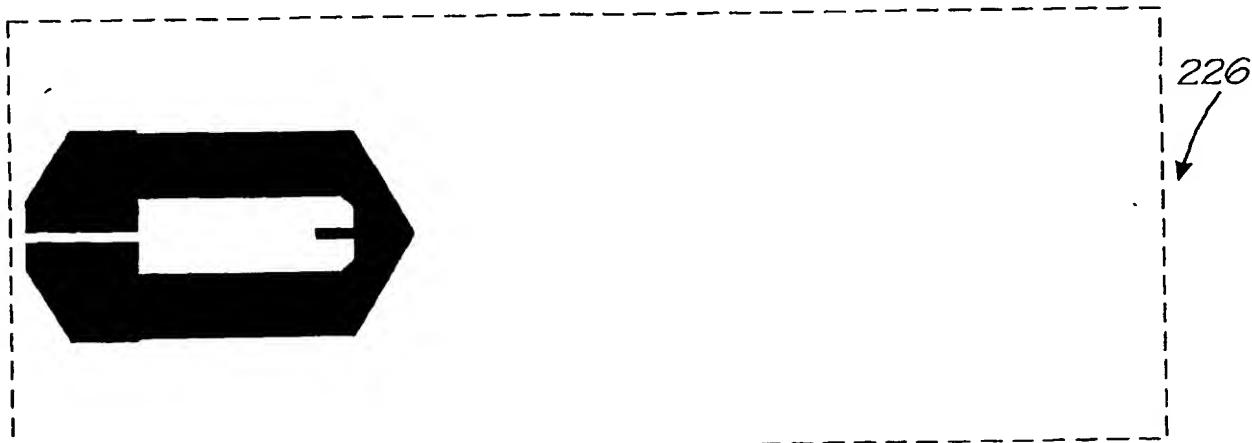


FIG. 38H

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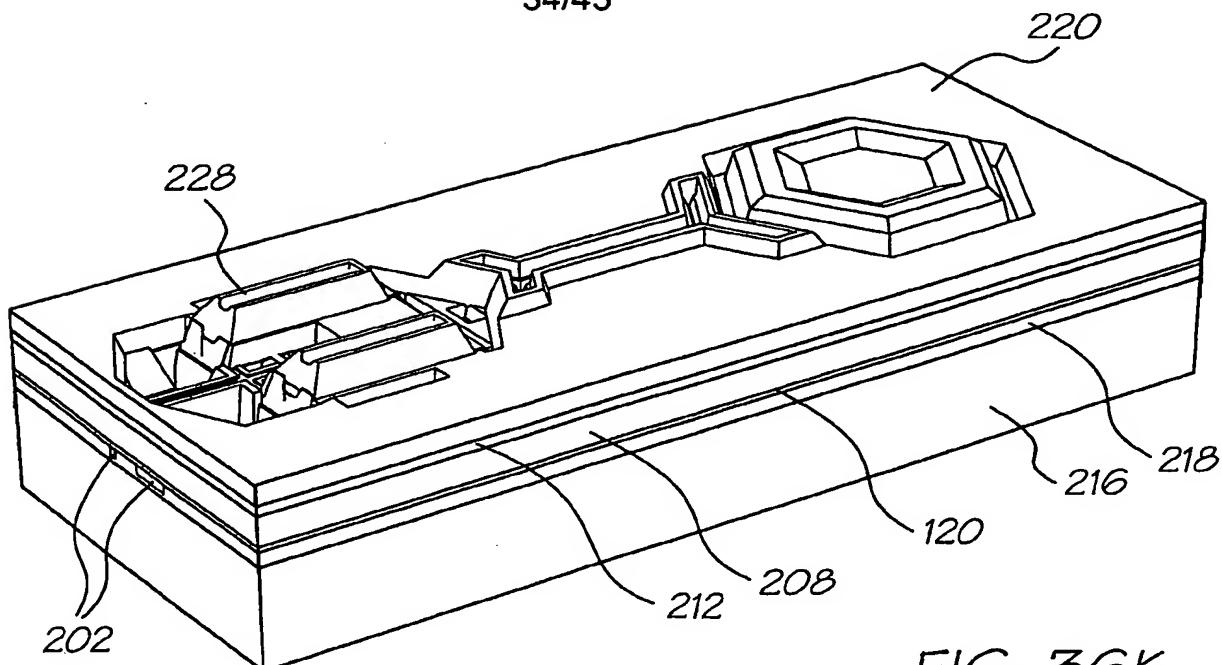


FIG. 36K

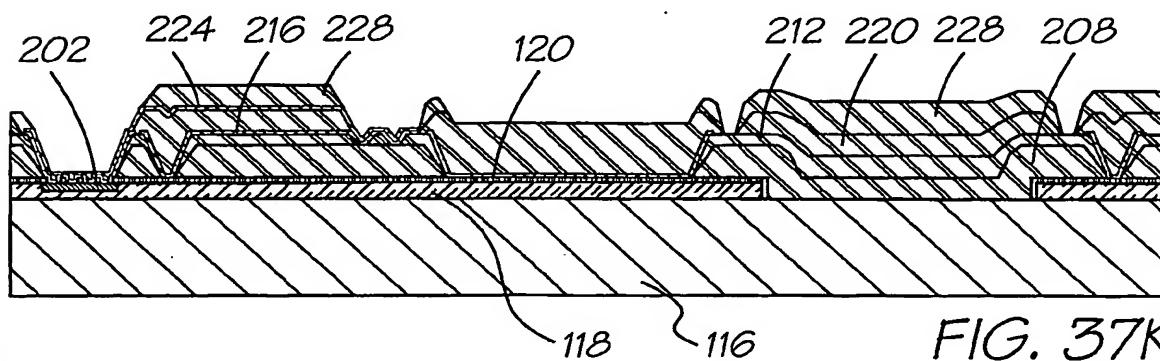


FIG. 37K

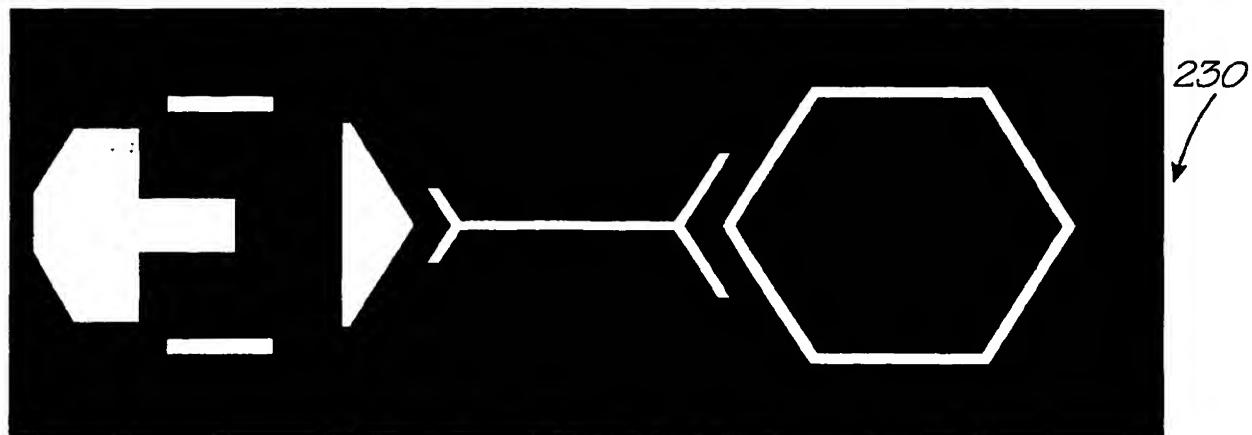


FIG. 38I

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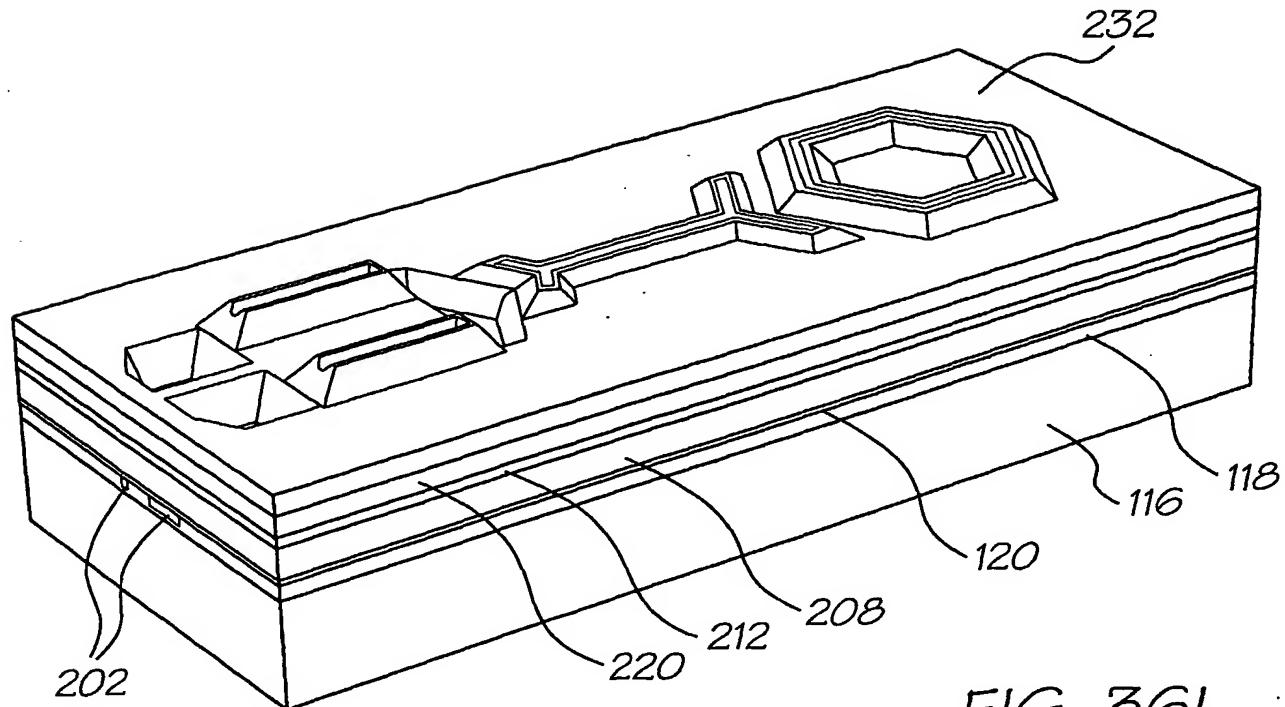


FIG. 36L

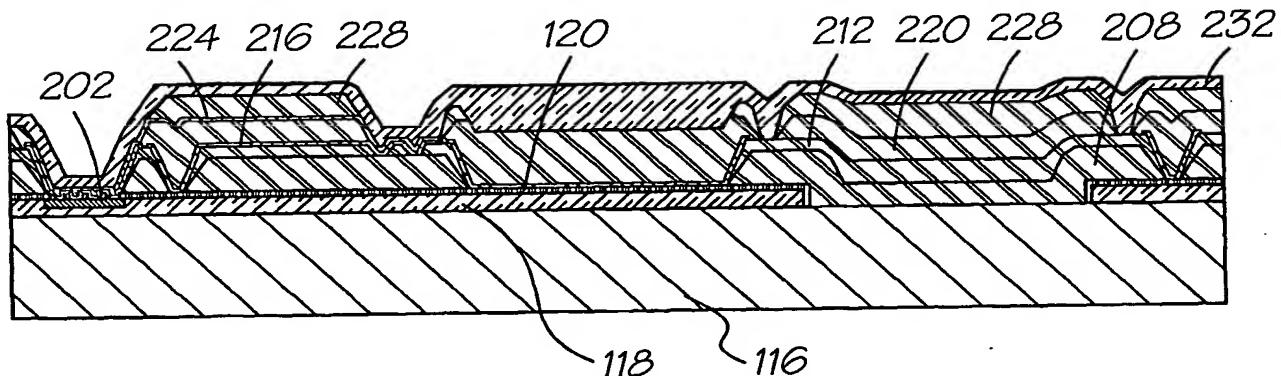


FIG. 37L

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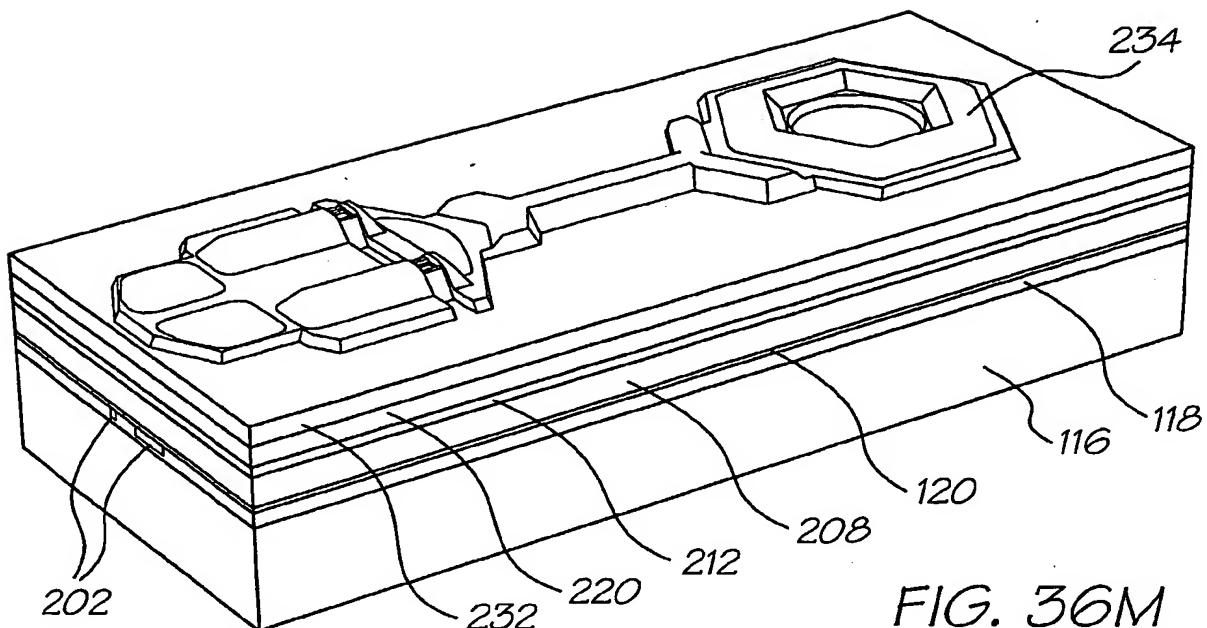


FIG. 36M

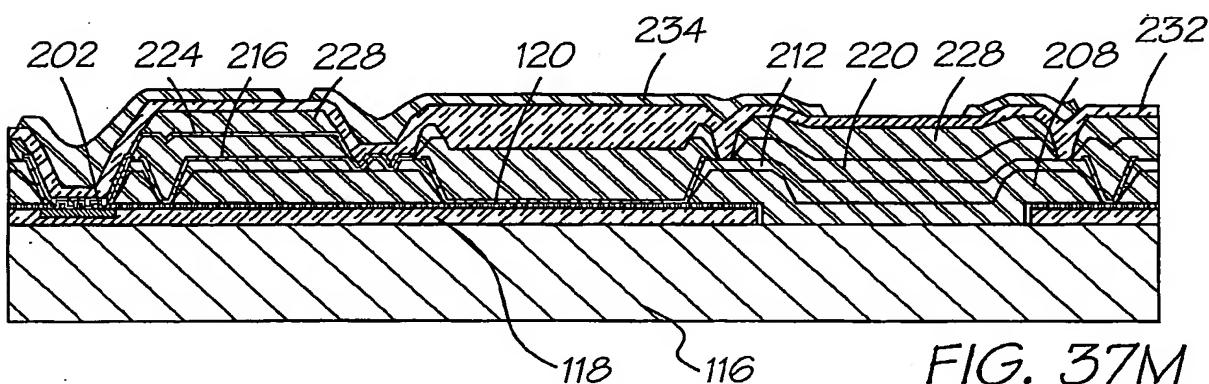


FIG. 37M

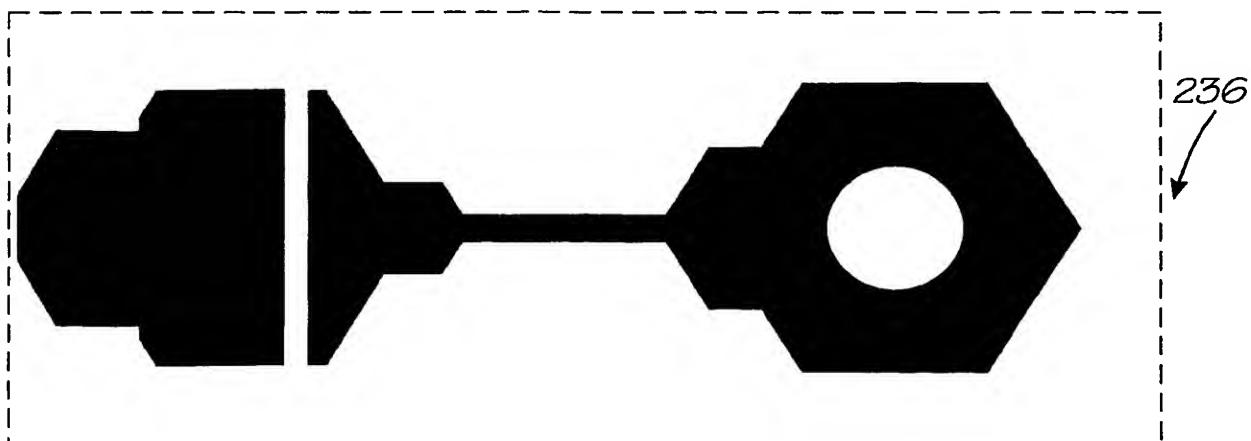


FIG. 38J

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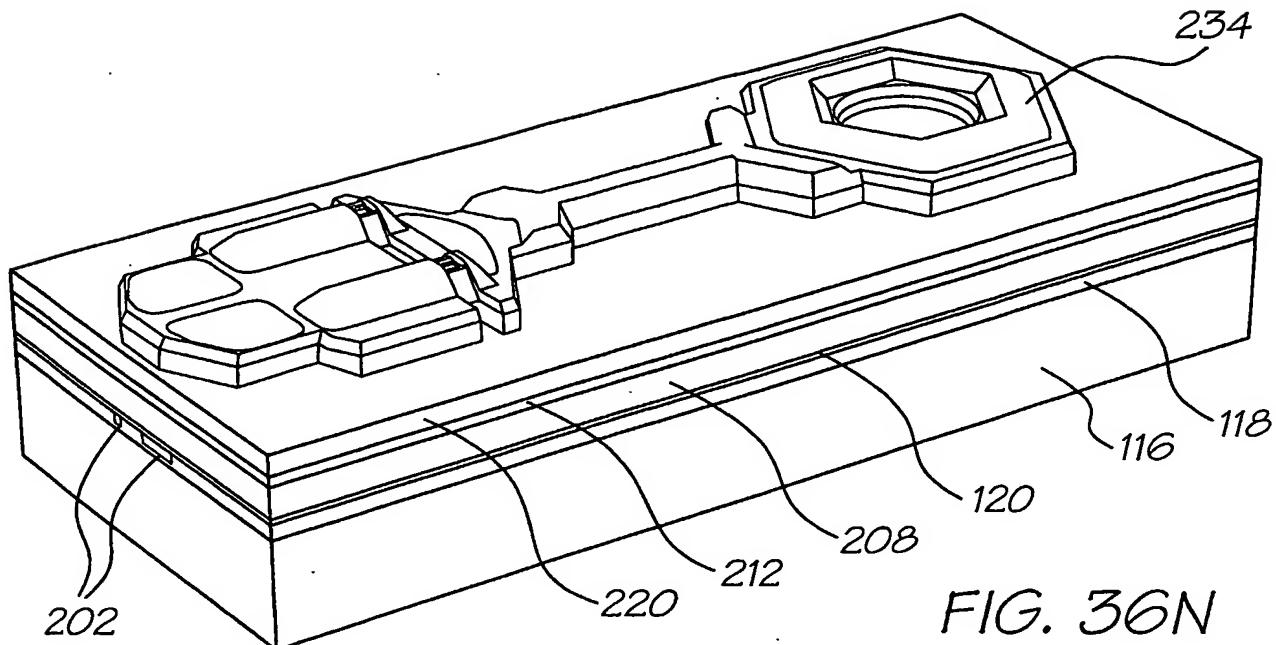


FIG. 36N

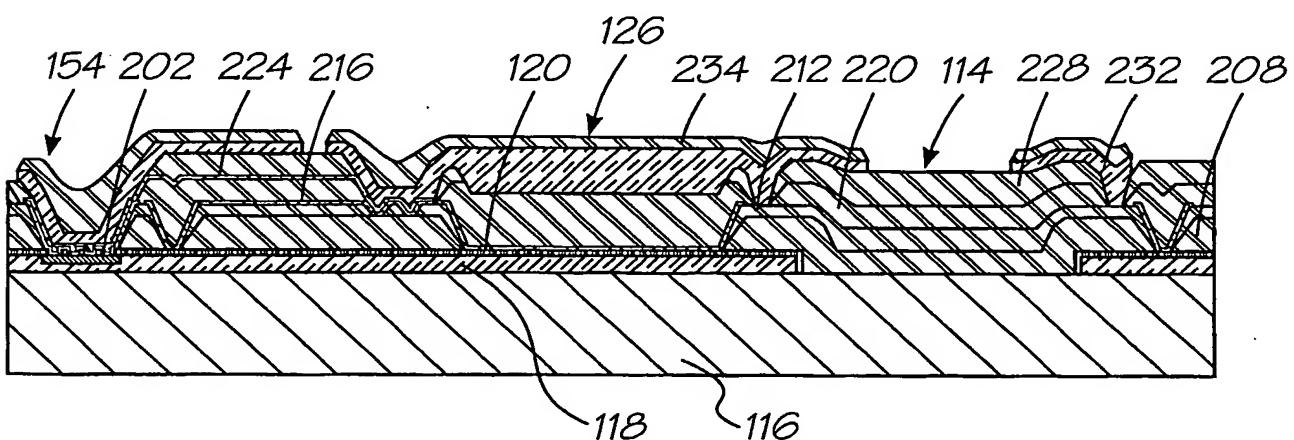
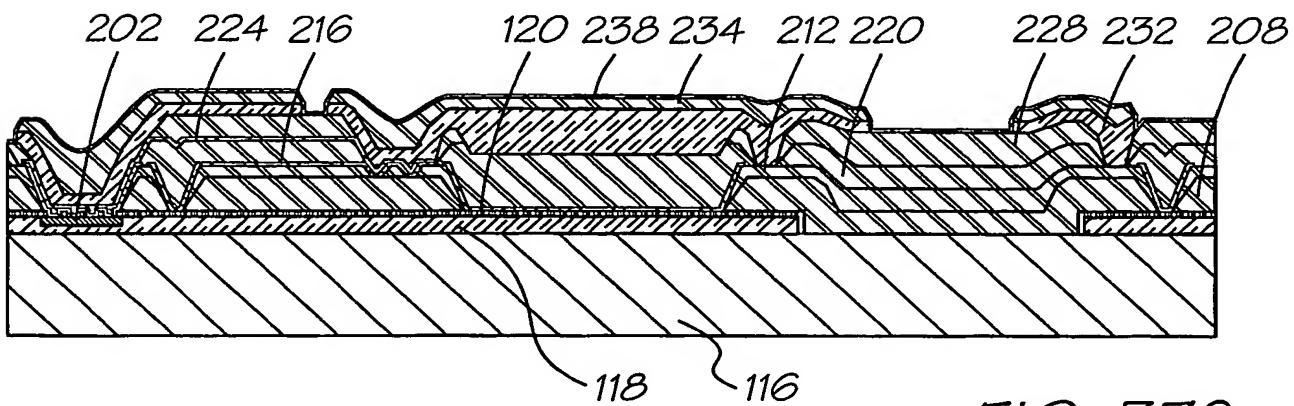
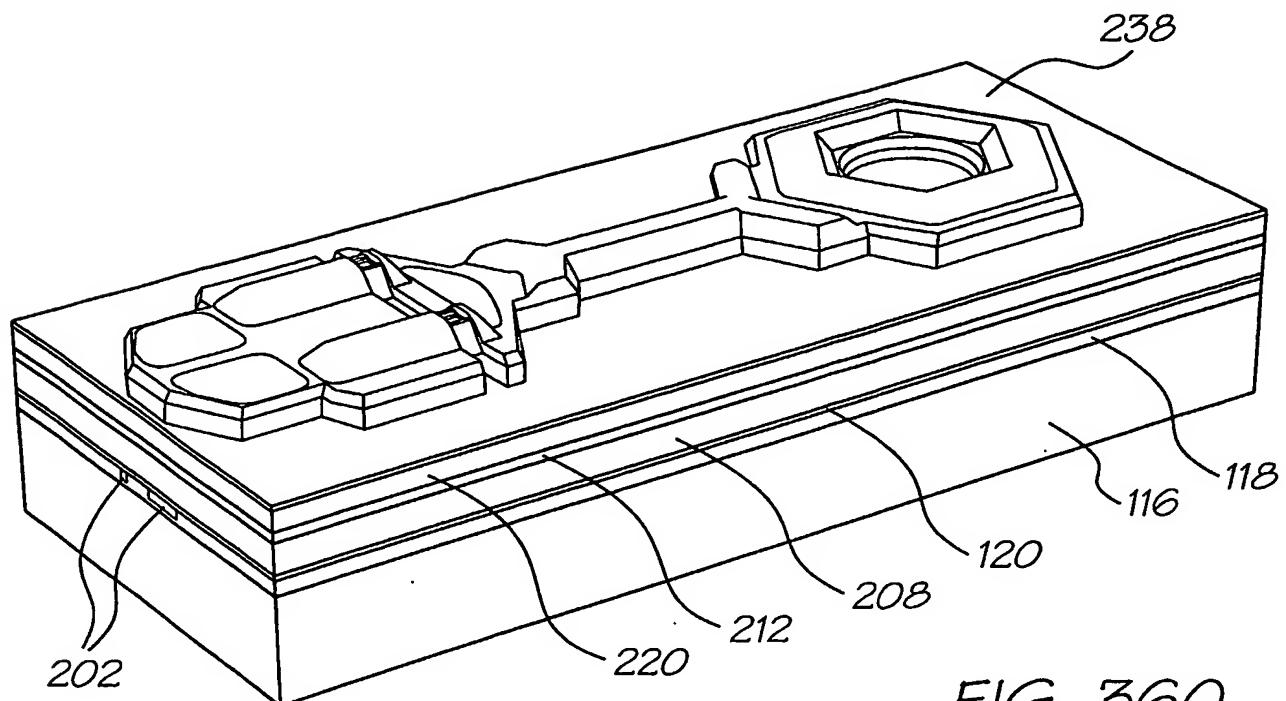
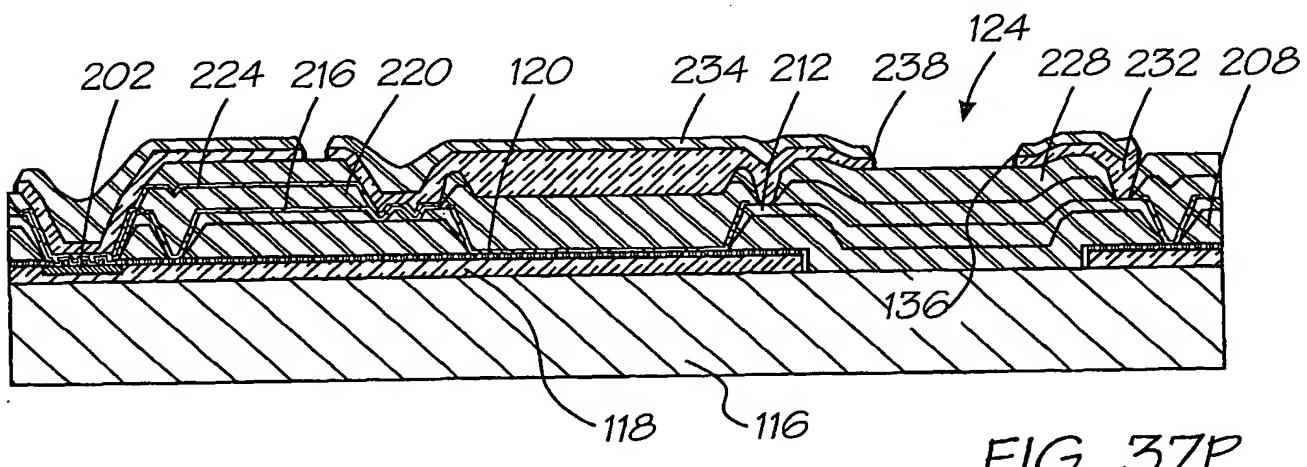
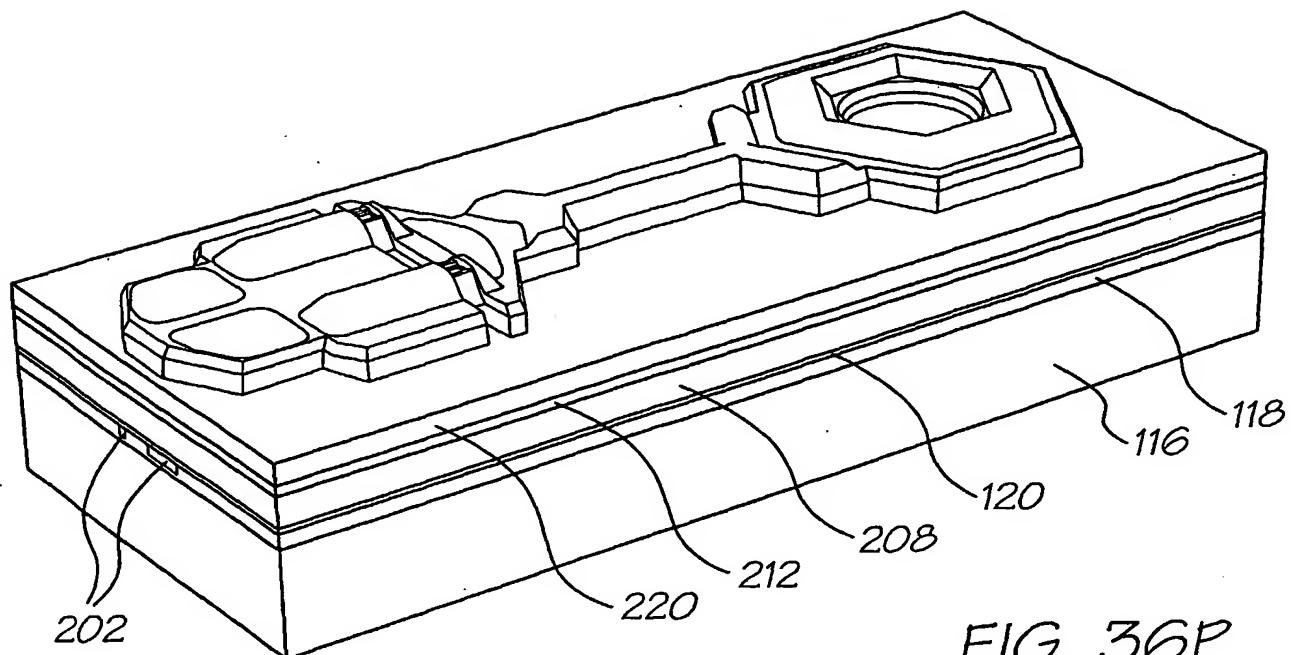


FIG. 37N

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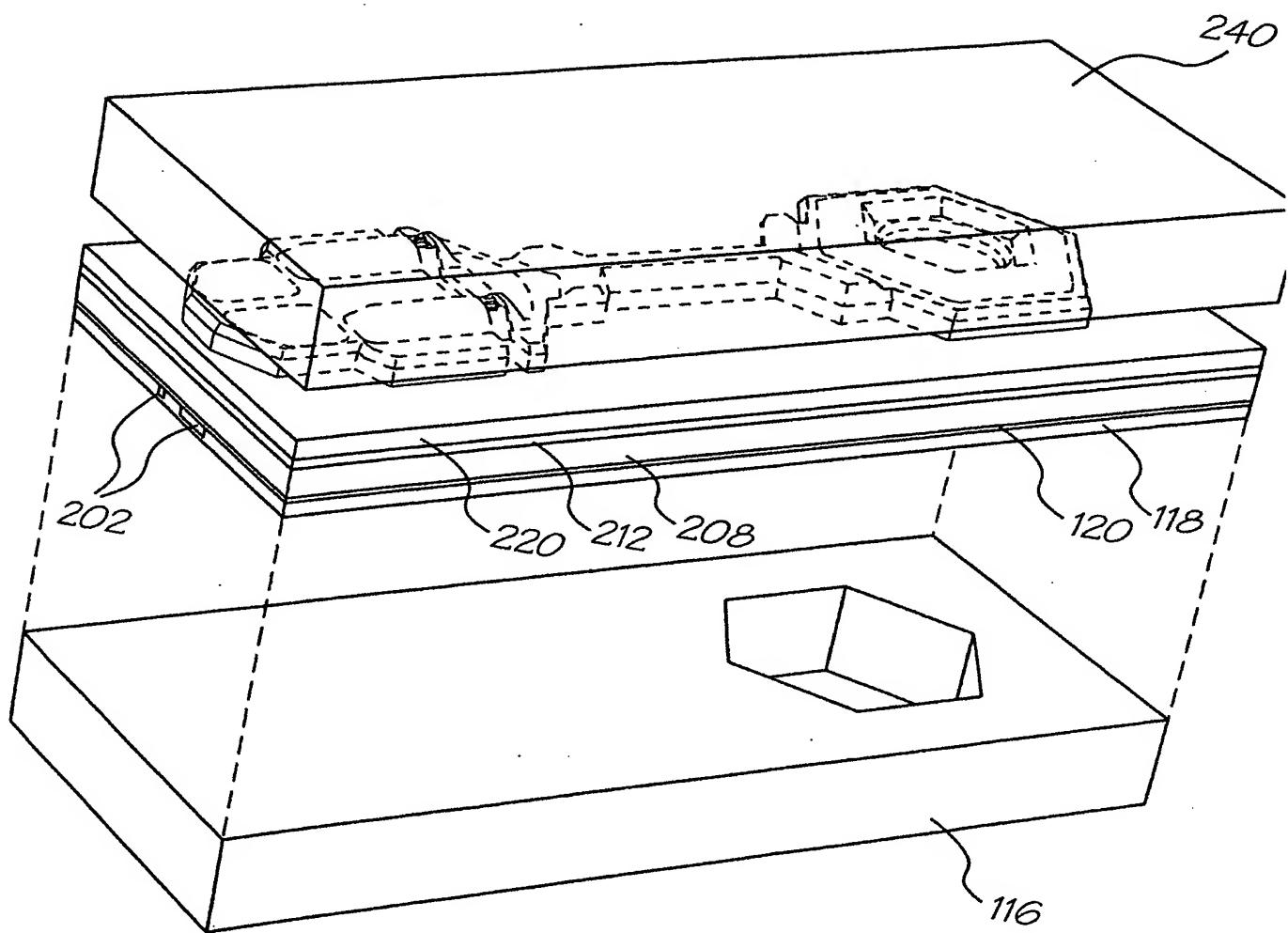


FIG. 36Q

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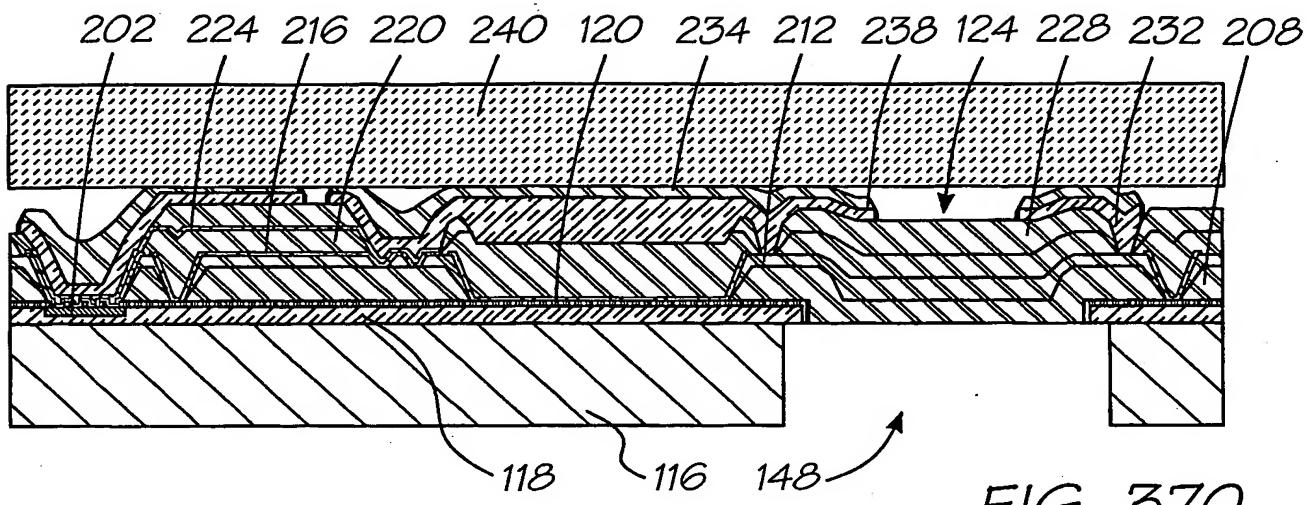


FIG. 37Q

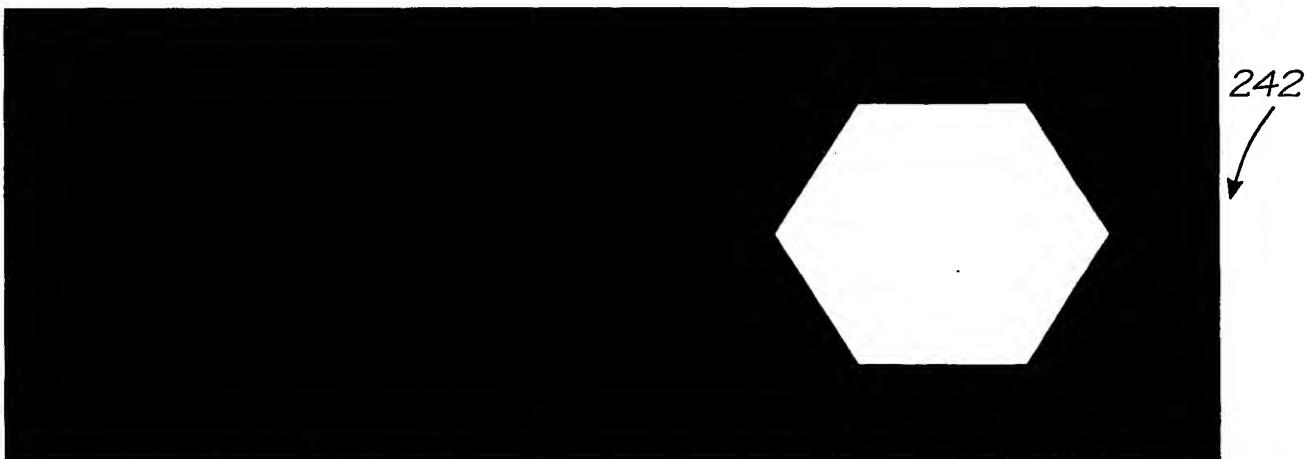


FIG. 38K

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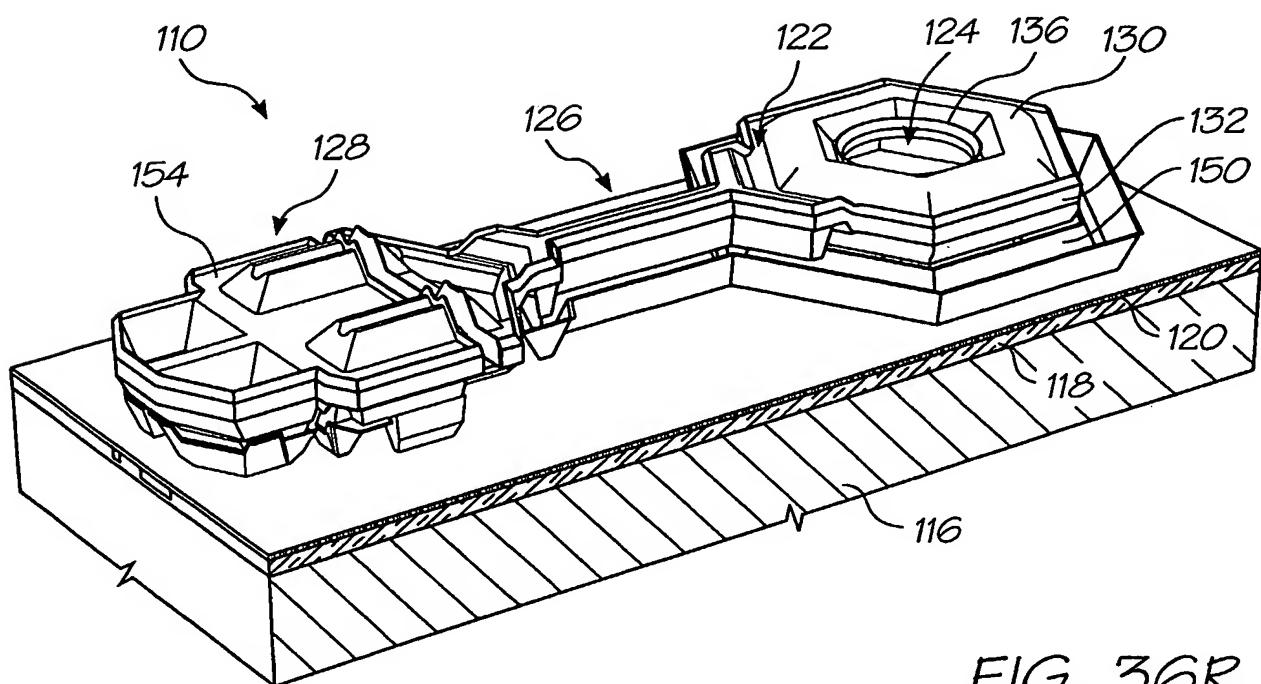


FIG. 36R

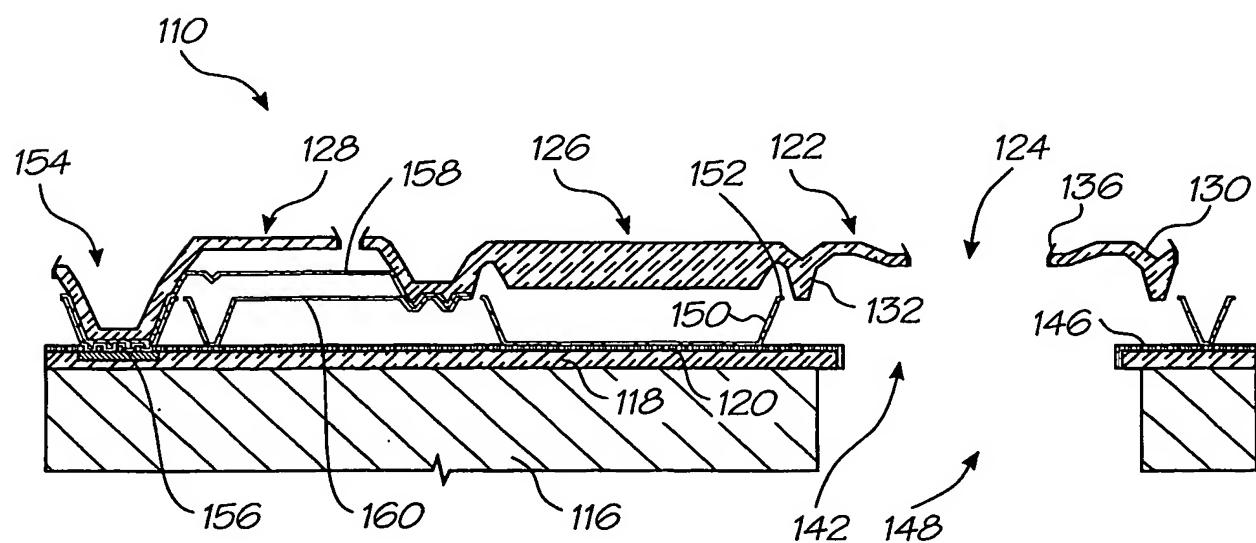


FIG. 37R

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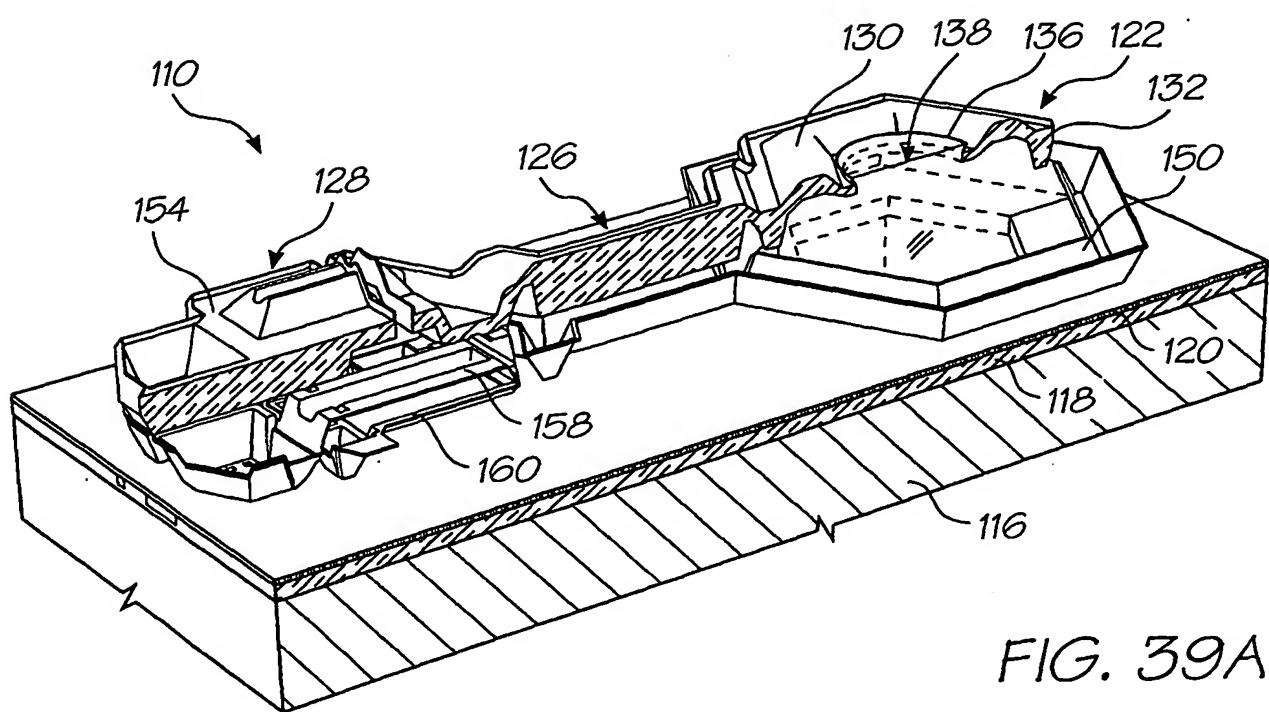


FIG. 39A

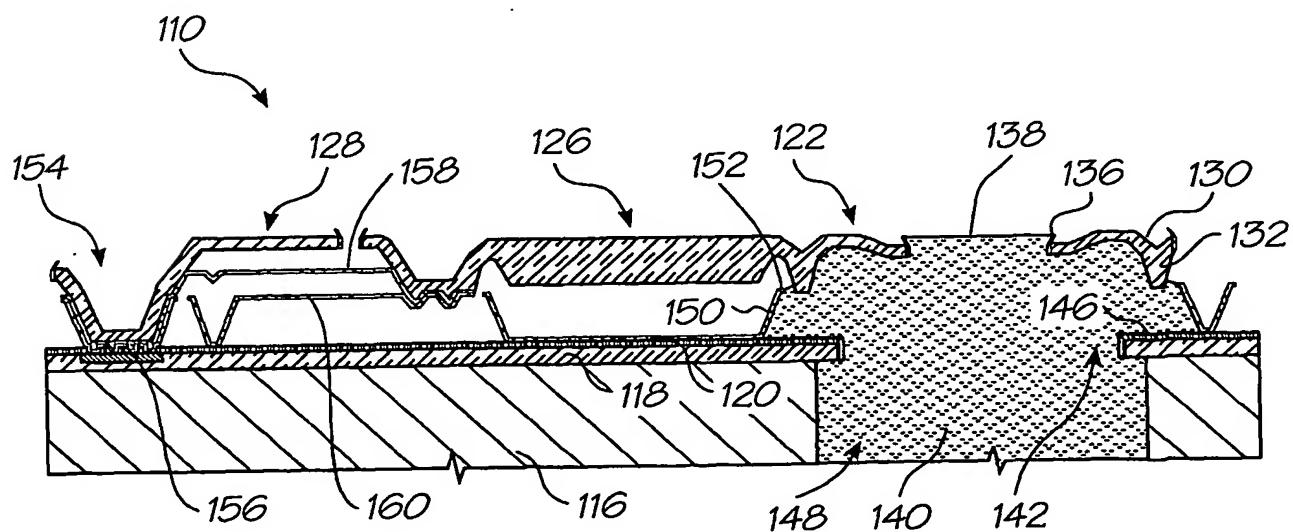


FIG. 40A

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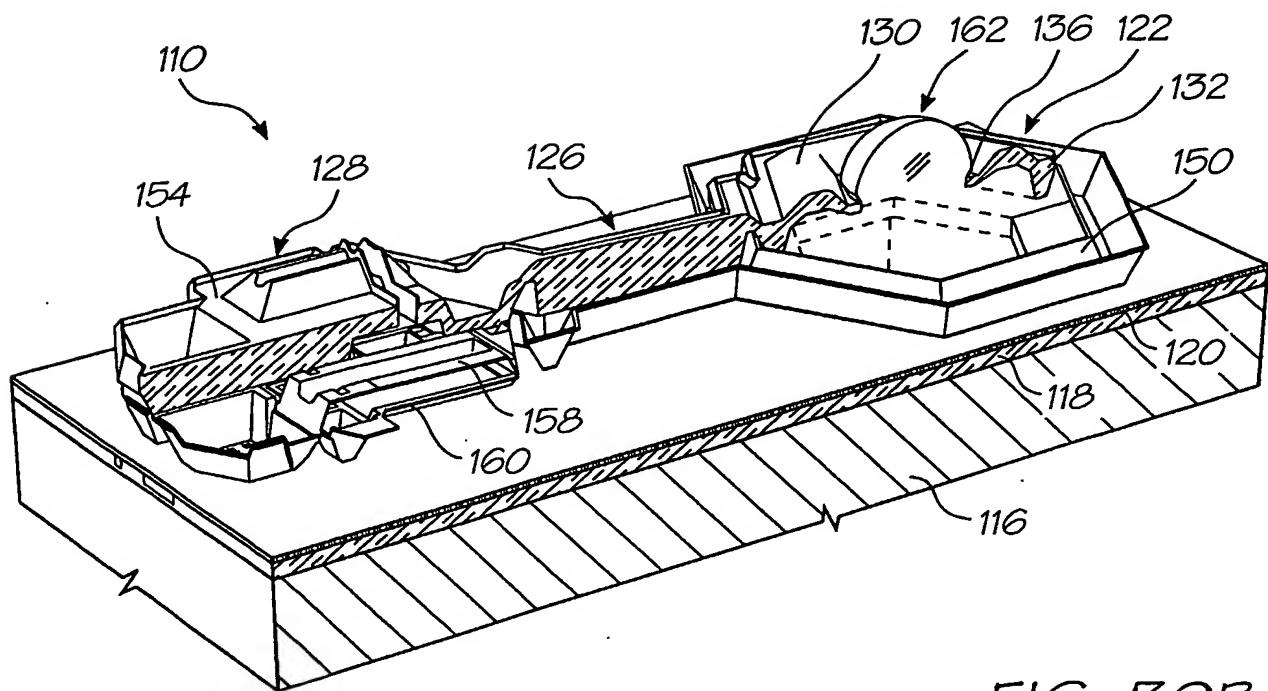


FIG. 39B

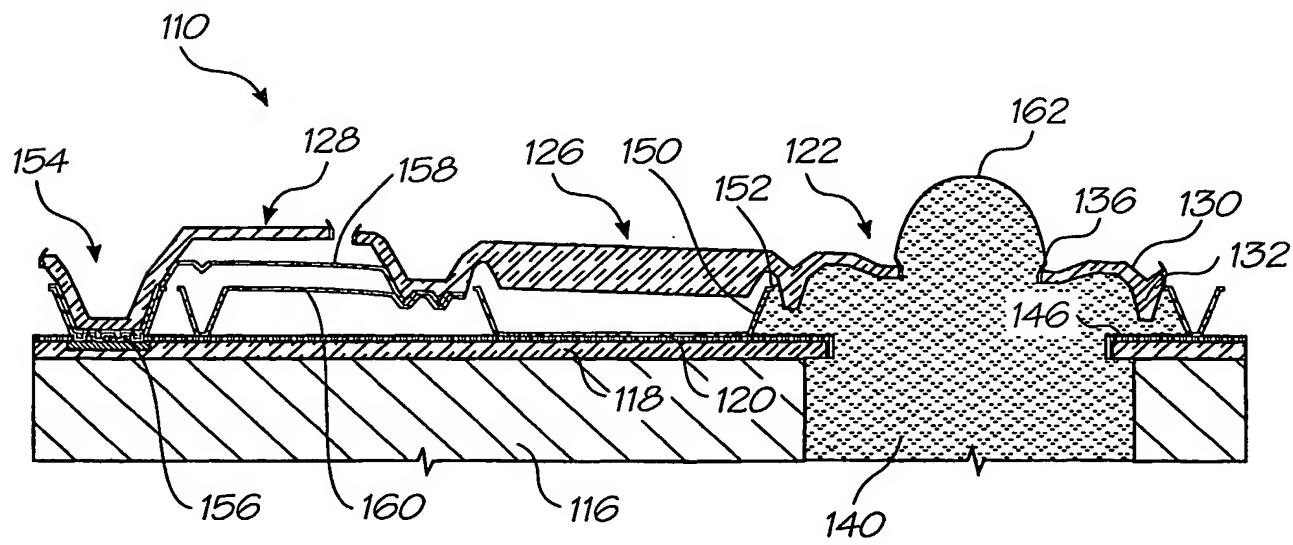


FIG. 40B

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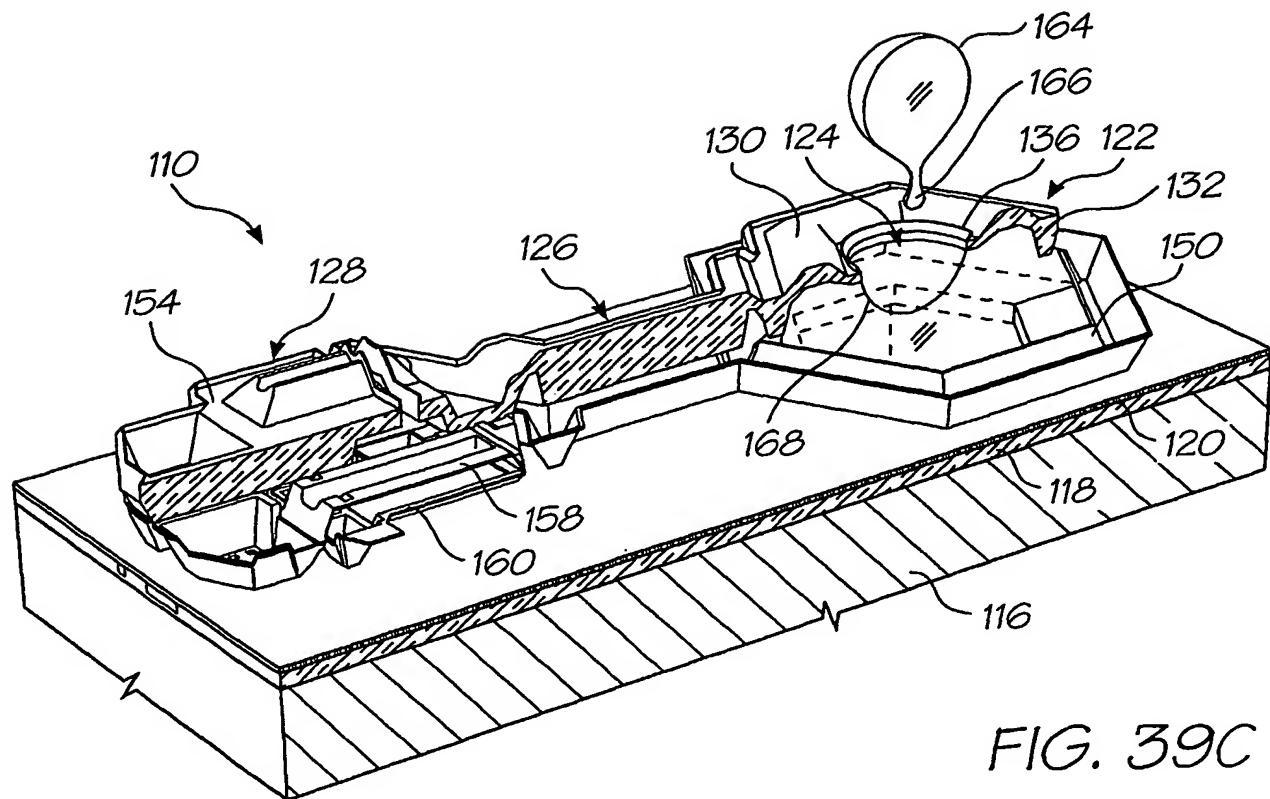


FIG. 39C

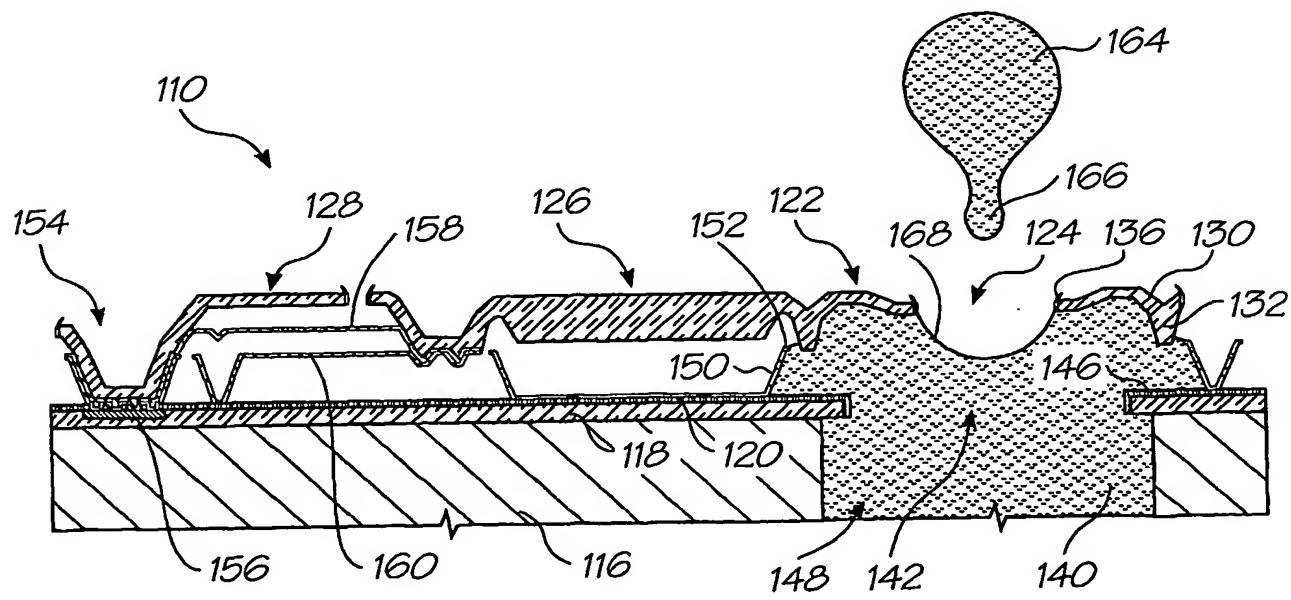


FIG. 40C